# 軍商兩用貨品及技術出口管制清單及一般軍用貨品清單

# 新、舊版修正對照與翻譯

## 編列說明

1. 軍商兩用貨品及技術出口管制清單列入第一項，一般軍用貨品清單列入第二項。

2. 本對照表列出下列情況：

    a. 中文有增/刪語詞，原意有所變動者；

    b. 舊版無、新版新增之內容；

    c. 舊版有、新版刪除之內容；

3. 本對照表未列出下列情況，但已於檔案中進行修正，與現行公布英文版本一致：

    a. 標點符號變動、專有名詞單引號或雙引號變動、CAS 編號前加註 CAS 字樣者；

    b. 英文編輯改變，未改變原有內容意義者；

    c. 排版方式變更，未改變原有內容意義者；

    d. 既有版本的錯字與誤植。

4. 為符合國際文體指南(2015 年版)，英文版本以逗號分隔整數與小數，以空間分隔表明千位整數。

# 目錄

# 第一項：軍商兩用貨品及技術出口管制清單修正對照表(黃色標示是修正差異)

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| 一般註解 | 1. 為管制以軍事用途設計或修訂的貨品，參考個別會員國對於軍用貨品管制相關清單，本清單參考文獻之〝參照軍用貨品管制〞指的是同一清單。 | 1.為管制以軍事用途設計或修訂的貨品，參考歐盟個別會員國對於歐盟軍用貨品管制相關清單，本清單參考文獻之〝參照軍用貨品管制〞指的是同一清單。 | 1.For control of goods which are designed or modified for military use, see the relevant list(s) of controls on military goods maintained by individual EU Member States. References in this Annex that state "SEE ALSO MILITARY GOODS CONTROLS" refer to the same lists. | 1. For control of goods which are designed or modified for military use, see the Common Military List of the European Union and relevant list(s) of controls on military goods maintained by individual EU Member States. References in this Annex that state "SEE ALSO MILITARY GOODS CONTROLS" refer to the same lists. |
| 一般註解 | 4. 在部分情況下，化學品依其名稱及 CAS 號碼加以臚列。本清單則是以具有相同結構式(包括水合物)的化學品為適用對象，而不論其名稱及 CAS 號碼如何。此處之所以提供 CAS 號碼，目的僅是在協助識別特定化學物或混合物，不受其命名法所困擾。由於某些表列化學品在不同形式之下，分別有著不同的 CAS 編號，且某些含有表列化學品的混合物亦另有其 CAS 編號，使用者不宜將 CAS 編號做為獨特識別工具。 | 4. 在部分情況下，化學品依其名稱及 CAS 號碼加以臚列。本清單則是以具有相同結構式(包括水合物、同位素標記形式或所有可能的立體異構體)的化學品為適用對象，而不論其名稱及 CAS 號碼如何。此處之所以提供 CAS 號碼，目的僅是在協助識別特定化學物或混合物，不受其命名法所困擾。由於某些表列化學品在不同形式之下，分別有著不同的 CAS 編號，且某些含有表列化學品的混合物亦另有其 CAS 編號，使用者不宜將 CAS 編號做為獨特識別工具。 | 4.In some instances chemicals are listed by name and CAS number. The list applies to chemicals of the same structural formula (including hydrates) regardless of name or CAS number. CAS numbers are shown to assist in identifying a particular chemical or mixture, irrespective of nomenclature. CAS numbers cannot be used as unique identifiers because some forms of the listed chemical have different CAS numbers, and mixtures containing a listed chemical may also have different CAS numbers. | 4. In some instances, chemicals are listed by name and CAS number. The list applies to chemicals of the same structural formula (including hydrates, isotopically-labelled forms or all possible stereoisomers) regardless of name or CAS number. CAS numbers are shown to assist in identifying a particular chemical or mixture, irrespective of nomenclature. CAS numbers cannot be used as unique identifiers because some forms of the listed chemical have different CAS numbers, and mixtures containing a listed chemical may also have different CAS numbers. |
| 1A004.d 技術註解 | 〝痕跡檢測〞之定義為能檢測少於 1 ppm 之蒸汽，或 1 mg 之固體或液體。 | 就 1A004.d.目的，〝痕跡檢測〞之定義為能檢測少於 1 ppm 之蒸汽，或 1 mg 之固體或液體。 | 'Trace detection' is defined as the capability to detect less than 1 ppm vapour, or 1 mg solid or liquid. | For the purposes of 1A004.d., 'trace detection' is defined as the capability to detect less than 1 ppm vapour, or 1 mg solid or liquid |

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| 1A008 技術註解 | ˋ塑形裝藥ˊ指以塑形方式裝填炸藥以集中爆炸效能。 | 就 1A008.a.目的，ˋ塑形裝藥ˊ指以塑形方式裝填炸藥以集中爆炸效能。 | 'Shaped charges' are explosive charges shaped to focus the effects of the explosive blast. | For the purposes of 1A008.a., 'shaped charges' are explosive charges shaped to focus the effects of the explosive blast. |
| 1B001 技術註解 1 | 1. 1B001 所述之ˋ主伺服定位ˊ軸，主要功用是在電腦程式指揮下，負責調控末端作用器(即端頭)相對於工件在空間上之位置，使其保持正確導向及方向，以順利達成所需求的流程。 | 1. 1B001 所述之ˋ主伺服定位ˊ軸，主要功用是在電腦〝程式〞指揮下，負責調控末端作用器(即端頭)相對於工件在空間上之位置，使其保持正確導向及方向，以順利達成所需求的流程。 | 1.For the purpose of 1B001, 'primary servo positioning' axes control, under computer program direction, the position of the end effector (i.e., head) in space relative to the work piece at the correct orientation and direction to achieve the desired process. | 1.For the purpose of 1B001, 'primary servo positioning' axes control, under computer "program" direction, the position of the end effector (i.e., head) in space relative to the work piece at the correct orientation and direction to achieve the desired process. |
| 1C001.a 註解 1.c.1 技術註解 | 1C001.a.註解 1.c.1.所述之吸收測試樣品應為正方形，其邊長至少為中心頻率 5 個波長以上，且置於幅射元件之遠場以內者。 | 就 1C001.a.目的，註解 1.c.1.所述之吸收測試樣品應為正方形，其邊長至少為中心頻率 5 個波長以上，且置於幅射元件之遠場以內者。 | Absorption test samples for 1C001.a. Note: 1.c.1. should be a square at least 5 wavelengths of the centre frequency on a side and positioned in the far field of the radiating element. | For the purposes of 1C001.a. Note: 1.c.1., absorption test samples should be a square at least 5 wavelengths of the centre frequency on a side and positioned in the far field of the radiating element. |
| 1C001.a 註解 e 技術註解 | ˋ開孔發泡ˊ為可彈性伸縮之多孔材料，其內部結構向大氣開放。ˋ開孔發泡ˊ也被稱作網狀發泡材料。 | 就 1C001.a.註解 1.e.目的，ˋ開孔發泡ˊ為可彈性伸縮之多孔材料，其內部結構向大氣開放。ˋ開孔發泡ˊ也被稱作網狀發泡材料。 | 'Open-cell foams' are flexible and porous materials, having an inner structure open to the atmosphere. 'Open-cell foams' are also known as reticulated foams. | For the purposes of 1C001.a. Note 1.e., 'open-cell foams' are flexible and porous materials, having an inner structure open to the atmosphere. 'Open-cell foams' are also known as reticulated foams. |
| 1C001.c 技術註解 | ˋ體積導電率ˊ及ˋ片(表面)電阻率ˊ應依 ASTM D-257 或等效國家標準測量。 | 就 1C001.c.目的，ˋ體積導電率ˊ及ˋ片(表面)電阻率ˊ應依 ASTM D-257 或等效國家標準測量。 | 'Bulk electrical conductivity' and 'sheet (surface) resistivity' should be determined using ASTM D-257 or national equivalents. | For the purposes of 1C001.c., 'bulk electrical conductivity' and 'sheet (surface) resistivity' should be determined using ASTM D-257 or national equivalents. |

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| 1C002 技術註解 | 1. 1C002 中之金屬合金係指含有所述金屬之重量百分比高於任一其他元素者。<br>2. ˋ應力斷裂壽命ˊ應依美國材料試驗學會(ASTM)標準 E-139 或等效國家標準測量。<br>3. ˋ低週期疲勞壽命ˊ應依 ASTM 標準 E-606ˋ固定振幅、低週期疲勞測試之建議程序ˊ進行,或依等效國家標準測量。測試應依軸向進行,其平均應力比為 1,且應力集中因數(Kt)亦為 1。平均應力比率之定義為最大應力減最小應力除以最大應力。 | 就 1C002 目的,金屬合金係指含有所述金屬之重量百分比高於任一其他元素者。 | 1. The metal alloys in 1C002 are those containing a higher percentage by weight of the stated metal than of any other element.<br>2. 'Stress-rupture life' should be measured in accordance with ASTM standard E-139 or national equivalents.<br>3. 'Low cycle fatigue life' should be measured in accordance with ASTM standard E-606 'Recommended Practice for Constant-Amplitude Low-Cycle Fatigue Testing' or national equivalents. Testing should be axial with an average stress ratio equal to 1 and a stress-concentration factor (Kt) equal to 1. The average stress ratio is defined as maximum stress minus minimum stress divided by maximum stress. | For the purposes of 1C002, metal alloys are those containing a higher percentage by weight of the stated metal than of any other element |
| 1C002.b 技術註解 | 無 | 就 1C002.b.目的:<br>1. ˋ應力斷裂壽命ˊ應依美國材料試驗學會(ASTM)標準 E-139 或等效國家標準測量。<br>2. ˋ低週期疲勞壽命ˊ應依 ASTM 標準 E-606ˋ固定振幅、低週期疲勞測試之建議程序ˊ進行,或依等效國家標準測量。測試應依軸向進行,其平均應力比為 1,且應力集中因數(Kt)亦為 1。平均應力比率之定義為最大應力減最小應力除以最大應力。 | - | For the purposes of 1C002.b.:<br><br>1.'Stress-rupture life' should be measured in accordance with ASTM standard E-139 or national equivalents.<br><br>2.'Low cycle fatigue life' should be measured in accordance with ASTM Standard E-606 'Recommended Practice for Constant-Amplitude Low-Cycle Fatigue Testing' or national equivalents. Testing should be axial with an average stress ratio equal to 1and a stress-concentration factor (Kt) equal to 1. The average stress ratio is defined as maximum stress minus minimum stress divided by maximum stress. |

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| 1C002.c.1 技術註解 | 以下所述之 X 相當於 1 個或以上合金元素。 | 就 1C002.c.1.目的，X 相當於 1 個或以上合金元素。 | X in the following equals one or more alloying elements. | For the purposes of 1C002.c.1., X equals one or more alloying elements. |
| 1C002 技術註解 | 無 | 就 1C002 目的： | - | For the purposes of 1C002, |
| 1C002 技術註解 10 | 10. ˋ快速凝固ˊ係指在冷卻率超過 1,000K/s 下，使熔態物質凝固之處理程序。 | 10.就 1C002 技術註解目的，ˋ快速凝固ˊ係指在冷卻率超過 1,000K/s 下，使熔態物質凝固之處理程序。 | 10. 'Solidify rapidly' is a process involving the solidification of molten material at cooling rates exceeding 1 000 K/sec. | 10. For the purposes of 1C002 Technical Notes, 'solidify rapidly' is a process involving the solidification of molten material at cooling rates exceeding 1 000 K/sec. |
| 1C003.a 技術註解 | 初始相對導磁率之測量必須於完全退火之材料上執行。 | 就 1C003.a.目的，初始相對導磁率之測量必須於完全退火之材料上執行。 | Measurement of initial relative permeability must be performed on fully anneled materials. | For the purposes of 1C003.a., measurement of initial relative permeability must be performed on fully annealed materials. |
| 1C003.c 技術註解 | 1C003.c.所述之 ˋ奈米結晶ˊ 材料係指具有晶體顆粒尺寸為 50 nm 或以下之材料，其晶體顆粒大小由 X 光繞射測定。 | 就 1C003.c.目的，ˋ奈米結晶ˊ 材料係指具有晶體顆粒尺寸為 50 nm 或以下之材料，其晶體顆粒大小由 X 光繞射測定。 | 'Nanocrystalline' materials in 1C003.c. are those materials having a crystal grain size of 50 nm or less, as determined by X-ray diffraction. | For the purposes of 1C003.c., 'nanocrystalline' materials are those materials having a crystal grain size of 50 nm or less, as determined by X-ray diffraction. |
| 1C008 技術註解 | 1. 1C008.a.2.熱塑性材料、1C008.a.4.材料與 1C008.f 材料之 ˋ玻璃轉換溫度(Tg)ˊ 測定，採用 ISO 11357-2(1999)所列之方式，或等效國家標準。<br>2. 1C008.a.2.熱塑性材料與 1C008.a.3.材料 ˋ玻璃轉換溫度(Tg)ˊ 測定，採用 ASTM D 7028-07 所列之 3 點彎曲法，或等效國家標準。該測試使用乾 | 1. 就 1C008.a.2.目的，熱塑性材料、1C008.a.4.材料與 1C008.f 材料之 ˋ玻璃轉換溫度(Tg)ˊ 測定，採用 ISO 11357-2(1999)所列之方式，或等效國家標準。<br>2. 就 1C008.a.2.目的，熱塑性材料與 1C008.a.3.材料 ˋ玻璃轉換溫度(Tg)ˊ 測定，採用 ASTM D 7028-07 所列之 3 點彎曲法，或等效國家標 | 1. The 'glass transition temperature (Tg)' for 1C008.a.2. thermoplastic materials, 1C008.a.4. materials and 1C008.f materials is determined using the method described in ISO 11357-2 (1999) or national equivalents<br>2. The 'glass transition temperature (Tg)' for 1C008.a.2. thermosetting materials and 1C008.a.3. materials is determined using the 3-point bend method described in ASTM D 7028-07 or equivalent national | 1. For the purposes of 1C008.a.2. thermoplastic materials, 1C008.a.4. materials and 1C008.f. materials, the 'glass transition temperature (Tg)' is determined using the method described in ISO 11357-2:1999 or national equivalents<br>2. For the purposes of 1C008.a.2. thermosetting materials and 1C008.a.3. materials, the 'glass transition temperature (Tg)' is determined using the 3-point bend method described in |

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| | 燥測試樣本進行測定,樣本之固化程度至少達到 ASTM E 2160-04 或等效國家標準所規範之 90 %,且其固化使用標準與後固化合併處理,以產生最高 Tg。 | 準。該測試使用乾燥測試樣本進行測定,樣本之固化程度至少達到 ASTM E 2160-04 或等效國家標準所規範之 90 %,且其固化使用標準與後固化合併處理,以產生最高 Tg。 | standard. The test is to be performed using a dry test specimen which has attained a minimum of 90 % degree of cure as specified by ASTM E 2160-04 or equivalent national standard, and was cured using the combination of standard- and post-cure processes that yield the highest Tg. | ASTM D 7028-07 or equivalent national standard. The test is to be performed using a dry test specimen which has attained a minimum of 90 % degree of cure as specified by ASTM E 2160-04 or equivalent national standard, and was cured using the combination of standard- and post-cure processes that yield the highest Tg. |
| 1C010 技術註解 | 1. 1C010.a.、 1C010.b.、1C010.c.或1C010.e.1.b.中之〝纖維或絲狀材料〞之〝比抗拉強度〞、〝比模數〞或比重,其抗拉強度與模量應使用 ISO 10618 (2004)或等效國家標準測定。 | 1.For the purpose of calculating "specific tensile strength", "specific modulus" or specific weight of "fibrous or filamentary materials" in 1C010.a., 1C010.b., 1C010.c. or 1C010.e.1.b., the tensile strength and modulus should be determined by using Method A described in ISO 10618:2004 or national equivalents. | 1. For the purpose of calculating "specific tensile strength", "specific modulus" or specific weight of "fibrous or filamentary materials" in 1C010.a., 1C010.b., 1C010.c. or 1C010.e.1.b., the tensile strength and modulus should be determined by using Method A described in ISO 10618 (2004) or national equivalents. | 1. For the purposes of calculating "specific tensile strength", "specific modulus" or specific weight of "fibrous or filamentary materials" in 1C010.a., 1C010.b., 1C010.c. or 1C010.e.1.b., the tensile strength and modulus should be determined by using Method A described in ISO 10618:2004 or national equivalents. |
| 1C010.d.2 技術註解 | 〝混合〞指熱塑性纖維絲與強化纖維絲之混合,以生產完全纖維型態之強化纖維〝基質〞混合物。 | 就 1C010.d.2.目的,〝混合〞指熱塑性纖維絲與強化纖維絲之混合,以生產完全纖維型態之強化纖維〝基質〞混合物。 | 'Commingled' is filament to filament blending of thermoplastic fibres and reinforcement fibres in order to produce a fibre reinforcement "matrix" mix in total fibre form. | For the purposes of 1C010.d.2., 'commingled' is filament to filament blending of thermoplastic fibres and reinforcement fibres in order to produce a fibre reinforcement "matrix" mix in total fibre form. |
| 1C010.e 技術註解 | 1.〝碳纖維預製品〞指在〝基質〞導入形成〝複合材料〞之前,佈或未塗佈之纖維為了組成一個架構之有序整齊排列。<br>2.1C010.e.所述材料的〝動態機械性分析玻璃轉換溫度(DMA Tg)〞,需採用 ASTM D 7028-07 所述方法,或等效國家標準,使用乾燥測試樣本進行測定。若為熱固性材料,該乾燥測試 | 1.就 1C010.e 和註解 1 目的,〝碳纖維預製品〞指在〝基質〞導入形成〝複合材料〞之前,佈或未塗佈之纖維為了組成一個架構之有序整齊排列。<br>2.就 1C010.e.2.材料目的,〝動態機械性分析玻璃轉換溫度(DMA Tg)〞,需採用 ASTM D 7028-07 所述方法,或等效國家標準,使用乾燥測試樣本進行測定。若為熱固性材料,該乾燥測 | 1.'Carbon fibre preforms' are an ordered arrangement of uncoated or coated fibres intended to constitute a framework of a part before the "matrix" is introduced to form a "composite".<br>2.The 'Dynamic Mechanical Analysis glass transition temperature (DMA Tg)' for materials specified in 1C010.e. is determined using the method described in ASTM D 7028-07, or equivalent national | 1. For the purposes of 1C010.e. and Note 1, 'carbon fibre preforms' are an ordered arrangement of uncoated or coated fibres intended to constitute a framework of a part before the "matrix" is introduced to form a "composite".<br>2. For the purposes of 1C010.e.2. materials, 'Dynamic Mechanical Analysis glass transition temperature (DMA Tg)' is determined using the method described in ASTM D 7028-07, or equivalent national standard, on a dry |

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| | 樣本之固化程度至少達到 ASTM E 2160-04 或等效國家標準所定義之 90%。 | 試樣本之固化程度至少達到 ASTM E 2160-04 或等效國家標準所定義之 90%。 | standard, on a dry test specimen. In the case of thermoset materials, degree of cure of a dry test specimen shall be a minimum of 90 % as defined by ASTM E 2160-04 or equivalent national standard. | test specimen. In the case of thermoset materials, degree of cure of a dry test specimen shall be a minimum of 90 % as defined by ASTM E 2160-04 or equivalent national standard. |
| 1C011.a 技術註解 | 鋯之鉿天然含量(一般在 2 % 至 7 %)，與鋯一同列入計算。 | 就 1C011.a.目的，鋯之鉿天然含量(一般在 2 % 至 7 %)，與鋯一同列入計算。 | The natural content of hafnium in the zirconium (typically 2 % to 7 %) is counted with the zirconium. | For the purposes of 1C011.a., the natural content of hafnium in the zirconium (typically 2 % to 7 %) is counted with the zirconium. |
| 1C012 技術註解 | 這些材料通常用於核熱源。 | 就 1C012 目的，這些材料通常用於核熱源。 | These materials are typically used for nuclear heat sources. | For the purposes of 1C012., these materials are typically used for nuclear heat sources. |
| 2A001.a 技術註解 | 1. ˋ環ˊ— 包含一或多個槽的徑向滾動軸承之環型部分 (ISO 5593:1997)。<br>2. ˋ滾動元件ˊ —在槽中滾動之滾珠或滾軸 (ISO 5593:1997)。 | 就 2A001.a.目的：<br>1. ˋ環ˊ— 包含一或多個槽的徑向滾動軸承之環型部分 (ISO 5593:1997)。<br>2. ˋ滾動元件ˊ —在槽中滾動之滾珠或滾軸 (ISO 5593:1997)。 | 1.'Ring' - annular part of a radial rolling bearing incorporating one or more raceways (ISO 5593:1997).<br>2.'Rolling element' - ball or roller which rolls between raceways (ISO 5593:1997). | For the purposes of 2A001.a.:<br>1. 'Ring' is a annular part of a radial rolling bearing incorporating one or more raceways (ISO 5593:1997).<br>2. 'Rolling element' is a ball or roller which rolls between raceways (ISO 5593:1997). |
| 2B 技術註解 | 1. 次平行輪廓軸(如臥式搪銑床之 w 軸，或中心線與主旋轉軸平行之次旋轉軸)不列入軌跡軸總數之計算。旋轉軸無需轉動 360˚。旋轉軸可由一線性元件(如螺桿或齒條及小齒輪組)驅動。 | 1. 就 2B 目的，次平行輪廓軸(如臥式搪銑床之 w 軸，或中心線與主旋轉軸平行之次旋轉軸)不列入軌跡軸總數之計算。旋轉軸無需轉動 360˚。旋轉軸可由一線性元件(如螺桿或齒條及小齒輪組)驅動。 | 1.Secondary parallel contouring axes, (e.g., the w-axis on horizontal boring mills or a secondary rotary axis the centre line of which is parallel to the primary rotary axis) are not counted in the total number of contouring axes. Rotary axes need not rotate over 360°. A rotary axis can be driven by a linear device (e.g., a screw or a rack-and-pinion). | 1. For the purposes of 2B, secondary parallel contouring axes, (e.g., the w-axis on horizontal boring mills or a secondary rotary axis the centre line of which is parallel to the primary rotary axis) are not counted in the total number of contouring axes. Rotary axes need not rotate over 360°. A rotary axis can be driven by a linear device (e.g., a screw or a rack-and-pinion). |
| 2B004 技術註解 | 腔室內部尺寸係指腔室內不包含夾具而可達到工作溫度及工作壓力之尺寸。該尺寸為壓力室或隔熱爐室之內徑，取其二者之間較小者，端視二室中何者位於另一者之內部而定。 | 就 2B004 目的，腔室內部尺寸係指腔室內不包含夾具而可達到工作溫度及工作壓力之尺寸。該尺寸為壓力室或隔熱爐室之內徑，取其二者之間較小者，端視二室中何者位於另一者之內 | The inside chamber dimension is that of the chamber in which both the working temperature and the working pressure are achieved and does not include fixtures. That dimension will be the smaller of either the inside | For the purposes of 2B004, the inside chamber dimension is that of the chamber in which both the working temperature and the working pressure are achieved and does not include fixtures. That dimension will be the smaller of either the inside diameter of |

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| | | 部而定。 | diameter of the pressure chamber or the inside diameter of the insulated furnace chamber, depending on which of the two chambers is located inside the other. | the pressure chamber or the inside diameter of the insulated furnace chamber, depending on which of the two chambers is located inside the other. |
| 2B006.a 技術註解 | 製造商規格上所訂定最精確座標測量機具(CMM)組態（如下列項目之最佳者：探針、針頭長度、運動參數及環境），並具有〝所有可補償機制〞者，其最大可容許長度量測誤差(E0,MPE)須達到 1.7+L/1,000 μm 之門檻。 | 就 2B006.a.目的，製造商規格上所訂定最精確座標測量機具(CMM)組態（如下列項目之最佳者：探針、針頭長度、運動參數及環境），並具有〝所有可補償機制〞者，其最大可容許長度量測誤差(E0,MPE)須達到 1.7+L/1,000 μm 之門檻。 | The E0,MPE of the most accurate configuration of the CMM specified by the manufacturer (e.g., best of the following: probe, stylus length, motion parameters, environment) and with "all compensations available" shall be compared to the 1,7+L/1 000 μm threshold. | For the purposes of 2B006.a., the E0,MPE of the most accurate configuration of the CMM specified by the manufacturer (e.g., best of the following: probe, stylus length, motion parameters, environment) and with "all compensations available" shall be compared to the 1,7 + L/1 000 μm threshold. |
| 2B006.b.1 技術註解 | 就 2B006.b.1.所述，〝非接觸式測量系統〞，其設計用於測量探針或被測量物在運動時，兩者沿著單一向量之間的距離。 | 就 2B006.b.1.目的：<br>1.〝非接觸式測量系統〞，其設計用於測量探針或被測量物在運動時，兩者沿著單一向量之間的距離；<br>2.〝量測範圍〞指最小與最大工作距離之間的距離。 | For the purposes of 2B006.b.1. 'non-contact type measuring systems' are designed to measure the distance between the probe and measured object along a single vector, where the probe or measured object is in motion. | For the purposes of 2B006.b.1.:<br>1. 'Non -contact type measuring systems' are designed to measure the distance between the probe and measured object along a single vector, where the probe or measured object is in motion.<br>2. 'Measuring range' means the distance between the minimum and maximum working distance. |
| 2B008.c 技術註解 | 〝複合迴轉工作台〞指可使工作物件在 2 個非平行軸線上旋轉與傾斜之工作台。 | 就 2B008.c.目的，〝複合迴轉工作台〞指可使工作物件在 2 個非平行軸線上旋轉與傾斜之工作台。 | A 'compound rotary table' is a table allowing the workpiece to rotate and tilt about two non-parallel axes | For the purposes of 2B008.c., a 'compound rotary table' is a table allowing the workpiece to rotate and tilt about two non-parallel axes. |
| 2B209.b | b. 轉子成型心軸，經設計用於形成內直徑介於 75 mm 至 400 mm 間之圓柱形轉子。 | b. 轉子成型心軸，經設計用於形成內直徑介於 75 mm 至 650 mm 間之圓柱形轉子。 | b.　Rotor-forming mandrels designed to form cylindrical rotors of inside diameter between 75 mm and 400 mm. | b.　Rotor-forming mandrels designed to form cylindrical rotors of inside diameter between 75 mm and 650 mm. |
| 2B228.c 技術註解 1 | 1. 內直徑介於 75 mm 至 400 mm 之間； | 1. 內直徑介於 75 mm 至 650 mm 之間； | 1.Inside diameter between 75 mm and 400 mm; | 1. Inside diameter between 75 mm and 650 mm; |

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| 2E003.b.1.c 技術註解 | ˋ直接作用液壓成形ˊ係指一種變形過程，使用充滿液體之彈性囊袋直接與工作物件接觸。 | 就 2E003.b.1.c.目的，ˋ直接作用液壓成形ˊ係指一種變形過程，使用充滿液體之彈性囊袋直接與工作物件接觸。 | 'Direct-acting hydraulic pressing' is a deformation process which uses a fluid-filled flexible bladder in direct contact with the workpiece. | For the purposes of 2E003.b.1.c., 'direct-acting hydraulic pressing' is a deformation process which uses a fluid filled flexible bladder in direct contact with the workpiece. |
| 3A001.a.2 技術註解 | ˋ非揮發性記憶體ˊ為電源關閉後儲存的資料在一陣時間內不會消失者的記憶體。 | 就 3A001.a.2.目的，ˋ非揮發性記憶體ˊ為電源關閉後儲存的資料在一陣時間內不會消失者的記憶體。 | 'Non-volatile memories' are memories with data retention over a period of time after a power shutdown. | For the purposes of 3A001.a.2., 'non-volatile memories' are memories with data retention over a period of time after a power shutdown. |
| 3A001.a.5.a 技術註解 | 1. n 位元之解析度係對應於一個量子化的 2n 種狀態。<br>2. 輸出字的位元數相等於數位—類比轉換器之解析度，有效位元數(ENOB)不用於判讀 ADC 之解析度。<br>3. 對於ˋ多頻道 ADCsˊ而言，〝取樣率〞非為匯總結果，且〝取樣率〞是指任何單一頻道之最大輸出率。<br>4. 對於ˋ交錯式 ADCsˊ或ˋ多頻道 ADCsˊ而言，〝取樣率〞為匯總結果，〝取樣率〞為所有交錯頻道之最大輸出率組合。 | 就 3A001.a.5.a.目的：<br>1. n 位元之解析度係對應於一個量子化的 2n 種狀態。<br>2. 輸出字的位元數相等於數位—類比轉換器之解析度，有效位元數(ENOB)不用於判讀 ADC 之解析度。<br>3. 對於ˋ多頻道 ADCsˊ而言，〝取樣率〞非為匯總結果，且〝取樣率〞是指任何單一頻道之最大輸出率。<br>4. 對於ˋ交錯式 ADCsˊ或ˋ多頻道 ADCsˊ而言，〝取樣率〞為匯總結果，〝取樣率〞為所有交錯頻道之最大輸出率組合。 | 1.A resolution of n bit corresponds to a quantisation of 2n levels.<br>2. The resolution of the ADC is the number of bits of the digital output that represents the measured analogue input. Effective Number of Bits (ENOB) is not used to determine the resolution of the ADC.<br>3. For "multiple channel ADCs", the "sample rate" is not aggregated and the "sample rate" is the maximum rate of any single channel.<br>4. For "interleaved ADCs" or for "multiple channel ADCs" that are specified to have an interleaved mode of operation, the "sample rates" are aggregated and the "sample rate" is the maximum combined total rate of all of the interleaved channels. | For the purposes of 3A001.a.5.a.:<br>1. A resolution of n bit corresponds to a quantisation of 2n levels.<br>2. The resolution of the ADC is the number of bits of the digital output that represents the measured analogue input. Effective Number of Bits (ENOB) is not used to determine the resolution of the ADC.<br>3. For "multiple channel ADCs", the "sample rate" is not aggregated and the "sample rate" is the maximum rate of any single channel.<br>4. For "interleaved ADCs" or for "multiple channel ADCs" that are specified to have an interleaved mode of operation, the "sample rates" are aggregated and the "sample rate" is the maximum combined total rate of all of the interleaved channels. |
| 3A001.a.5.b 技術註解 | 1. ˋ無雜訊動態範圍ˊ(SFDR)定義為以下兩數值之比：DAC 輸入點載波頻率(最大信號組件)的 RMS 數值，與輸出點次大之噪訊或諧波失真組件的 RMS 數值。 | 就 3A001.a.5.b.目的：<br>1. ˋ無雜訊動態範圍ˊ(SFDR)定義為以下兩數值之比：DAC 輸入點載波頻率(最大信號組件)的 RMS 數值，與輸出點次大之噪訊或諧波失真組件的 RMS 數值。 | 1.Spurious Free Dynamic Range' (SFDR) is defined as the ratio of the RMS value of the carrier frequency (maximum signal component) at the input of the DAC to the RMS value of the next largest noise or harmonic distortion component at its output. | For the purposes of 3A001.a.5.b.:<br>1. 'Spurious Free Dynamic Range' (SFDR) is defined as the ratio of the RMS value of the carrier frequency (maximum signal component) at the input of the DAC to the RMS value of the next largest noise or harmonic distortion component at its output. |

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| 3A001.a.7 技術註解 | 1. 3A001.a.7.a.中數位輸入/輸出埠之最大數量,亦可稱為最大使用者輸入/輸出埠量,或最大可用輸入/輸出埠量,無論積體電路已經封裝或是晶片。<br>2. ˋ總單向峰串列傳收器數據率ˊ為峰串列單向傳收器數據率乘以可場程式閘陣列收發器數量之乘積。 | 就 3A001.a.7.目的:<br>1. 3A001.a.7.a.中數位輸入/輸出埠之最大數量,亦可稱為最大使用者輸入/輸出埠量,或最大可用輸入/輸出埠量,無論積體電路已經封裝或是晶片。<br>2. ˋ總單向峰串列傳收器數據率ˊ為峰串列單向傳收器數據率乘以可場程式閘陣列收發器數量之乘積。 | 1.Maximum number of digital input/outputs in 3A001.a.7.a. is also referred to as the maximum user input/outputs or maximum available input/outputs, whether the integrated circuit is packaged or bare die.<br><br>2.'Aggregate one-way peak serial transceiver data rate' is the product of the peak serial one-way transceiver data rate times the number of transceivers on the FPGA. | For the purposes of 3A001.a.7.:<br>1. Maximum number of digital input/outputs in 3A001.a.7.a. is also referred to as the maximum user input/outputs or maximum available input/outputs, whether the integrated circuit is packaged or bare die.<br>2. 'Aggregate one-way peak serial transceiver data rate' is the product of the peak serial one-way transceiver data rate times the number of transceivers on the FPGA. |
| 3A001.a.12 技術註解 | 當 N 等於 1,024 點時,依 3A001.a.12.公式所得之執行時間為 500 $\mu$s。 | 就 3A001.a.12.目的,當 N 等於 1,024 點時,依 3A001.a.12.公式所得之執行時間為 500 $\mu$s。 | When N is equal to 1 024 points, the formula in 3A001.a.12. gives an execution time of 500 µs. | For the purposes of 3A001.a.12., when N is equal to 1 024 points, the formula gives an execution time of 500 µs. |
| 3A001.a.13 技術註解 | DAC 時脈頻率可指定為主時脈頻率或輸入時脈頻率。 | 就 3A001.a.13.目的,DAC 時脈頻率可指定為主時脈頻率或輸入時脈頻率。 | The DAC clock frequency may be specified as the master clock frequency or the input clock frequency. | For the purposes of 3A001.a.13., the DAC clock frequency may be specified as the master clock frequency or the input clock frequency. |
| 3A001.a.14 技術註解 | 1. n 位元之解析度係對應於一個量子化的 2n 種狀態。<br>2. 輸出字的位元數相等於數位－類比轉換器之解析度,有效位元數(ENOB)不用於判讀 ADC 之解析度。<br>3. 對於積體電路具非交錯式〝多頻道 ADCs〞而言,〝取樣率〞非匯總結果,且〝取樣率〞是指任何單一頻道之最大輸出率。<br>4. 對於積體電路具〝交錯式 ADCs〞或〝多頻道 ADCs〞其操作具有交錯模式者,〝取樣率〞為匯總結果,〝取樣率〞為所有交錯頻道之最大輸出率組合。 | 就 3A001.a.14.目的:<br>1. n 位元之解析度係對應於一個量子化的 2n 種狀態。<br>2. 輸出字的位元數相等於數位－類比轉換器之解析度,有效位元數(ENOB)不用於判讀 ADC 之解析度。<br>3. 對於積體電路具非交錯式〝多頻道 ADCs〞而言,〝取樣率〞非匯總結果,且〝取樣率〞是指任何單一頻道之最大輸出率。<br>4. 對於積體電路具〝交錯式 ADCs〞或〝多頻道 ADCs〞其操作具有交錯模式者,〝取樣率〞為匯總結果,〝取樣率〞為所有交錯頻道之最大輸出率 | 1.A resolution of n bit corresponds to a quantisation of 2 n levels.<br>2.The resolution of the ADC is the number of bits of the digital output of the ADC that represents the measured analogue input. Effective Number of Bits (ENOB) is not used to determine the resolution of the ADC.<br>3.For integrated circuits with non-interleaving "multiple channel ADCs", the "sample rate" is not aggregated and the "sample rate" is the maximum rate of any single channel.<br>4.For integrated circuits with "interleaved ADCs "or with "multiple channel ADCs" that are specified to have an interleaved mode of operation, the "sample rates" are aggregated and the "sample rate" is the maximum | For the purposes of 3A001.a.14.:<br>1. A resolution of n bit corresponds to a quantisation of 2n levels.<br>2. The resolution of the ADC is the number of bits of the digital output of the ADC that represents the measured analogue input. Effective Number of Bits (ENOB) is not used to determine the resolution of the ADC.<br>3. For integrated circuits with non-interleaving "multiple channel ADCs", the "sample rate" is not aggregated and the "sample rate" is the maximum rate of any single channel.<br>4. For integrated circuits with "interleaved ADCs "or with "multiple channel ADCs" that are specified to have an interleaved mode of operation, |

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| | | 組合。 | combined total rate of all of the interleaved channels. | the "sample rates" are aggregated and the "sample rate" is the maximum combined<br>total rate of all of the interleaved channels. |
| 3A001.b.1.d 技術註解 | ˋ雙重模式ˊ指〝真空電子元件〞束電流能透過柵控在連續波與脈衝模式之間改變，其產生之尖峰脈衝輸出功率大於連續波輸出功率。 | 就 3A001.b.1.d.目的，ˋ雙重模式ˊ指〝真空電子元件〞束電流能透過柵控在連續波與脈衝模式之間改變，其產生之尖峰脈衝輸出功率大於連續波輸出功率。 | 'Dual mode' means the 'vacuum electronic device' beam current can be intentionally changed between continuous-wave and pulsed mode operation by use of a grid and produces a peak pulse output power greater than the continuous-wave output power. | For the purposes of 3A001.b.1.d., 'dual mode' means the "vacuum electronic device" beam current can be intentionally changed between continuous-wave and pulsed mode operation by use of a grid and produces a peak pulse output power greater than the continuous-wave output power. |
| 3A001.b.9 技術註解 | 1. 計算 3A001.b.9.b.所述之體積，如下例所示：最大評定功率 20W 之管制體積為 20 W×10 cm3/W＝200 cm3。<br>2. 3A001.b.9.a.所述之ˋ開機時間ˊ指的是完全關機到完全運作狀態之時間；亦即包括微波功率模組(MPM)熱機時間。 | 就 3A001.b.9.目的：<br>1. 計算 3A001.b.9.b.所述之體積，如下例所示：最大評定功率 20W 之管制體積為 20 W×10 cm3/W＝200 cm3。<br>2. 3A001.b.9.a.所述之ˋ開機時間ˊ指的是完全關機到完全運作狀態之時間；亦即包括微波功率模組(MPM)熱機時間。 | 1.To calculate the volume in 3A001.b.9.b., the following example is provided: for a maximum rated power of 20 W, the volume would be: 20 W × 10 cm3/W = 200 cm3.<br>2.The' turn-on time' in 3A001.b.9.a. refers to the time from fully-off to fully operational, i.e., it includes the warm-up time of the MPM. | For the purposes of 3A001.b.9.:<br>1. To calculate the volume in 3A001.b.9.b., the following example is provided: for a maximum rated power of 20 W, the volume would be: 20 W × 10 cm3/W = 200 cm3.<br>2. The'turn-on time' in 3A001.b.9.a. refers to the time from fully-off to fully operational, i.e., it includes the warm up time of the MPM. |
| 3A001.b..10 技術註解 | 在 3A001.b.10.中，F 為以 Hz 為單位之操作頻率之偏離值，而 f 為以 MHz 為單位之操作頻率； | 就 3A001.b.10.目的，F 為以 Hz 為單位之操作頻率之偏離值，而 f 為以 MHz 為單位之操作頻率； | In 3A001.b.10., F is the offset from the operating frequency in Hz and f is the operating frequency in MHz. | For the purposes of 3A001.b.10., F is the offset from the operating frequency in Hz and f is the operating frequency in MHz. |
| 3A001.b.11 技術註解 | 〝頻率合成器〞係指任何種類頻率來源不論實際使用之技術，能由多個輸出提供多個同步或交替之輸出頻率，而該等頻率由較少數之標準(或主要)頻率所控制、產生或規範。 | 就 3A001.b.11.目的，〝頻率合成器〞係指任何種類頻率來源不論實際使用之技術，能由多個輸出提供多個同步或交替之輸出頻率，而該等頻率由較少數之標準(或主要)頻率所控制、產生或規範。 | A 'frequency synthesiser' is any kind of frequency source, regardless of the actual technique used, providing a multiplicity of simultaneous or alternative output frequencies, from one or more outputs, controlled by, derived from or disciplined by a lesser number of standard (or master) frequencies. | For the purposes of 3A001.b.11., a 'frequency synthesiser' is any kind of frequency source, regardless of the actual technique used, providing a multiplicity of simultaneous or alternative output frequencies, from one or more outputs,<br>controlled by, derived from or disciplined by a lesser number of standard (or master) frequencies. |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| 3A001.b.12 技術註解 | 1.〝傳輸/接收模組〞為一多功能〝電子組裝〞，可為傳輸與接收信號提供雙向振幅與相位控制。<br>~ | 就 3A001.b.12.目的：<br>1.〝傳輸/接收模組〞為一多功能〝電子組裝〞，可為傳輸與接收信號提供雙向振幅與相位控制。<br>~~ | 1. A 'transmit/receive module': is a multifunction "electronic assembly" that provides bi-directional amplitude and phase control for transmission and reception of signals.<br>~~ | For the purposes of 3A001.b.12.:<br>1. A 'transmit/receive module': is a multifunction "electronic assembly" that provides bi-directional amplitude and phase control for transmission and reception of signals.<br>~~ |
| 3A001.c.1 技術註解 | 〝頻率旁帶排斥〞指數據表中最大排斥值。 | 就 3A001.c.1.目的，〝頻率旁帶排斥〞指數據表中最大排斥值。 | 'Frequency side-lobe rejection' is the maximum rejection value specified in data sheet. | For the purposes of 3A001.c.1., 'frequency side-lobe rejection' is the maximum rejection value specified in data sheet. |
| 3A001.e.4 技術註解 | 〝AM0〞或〝空氣質量零〞，指的是當太陽與地球之距離為一個天文單位(AU)時，太陽光在地球外大氣層之光譜輻射照度。 | 就 3A001.e.4.目的，〝AM0〞或〝空氣質量零〞，指的是當太陽與地球之距離為一個天文單位(AU)時，太陽光在地球外大氣層之光譜輻射照度。 | 'AM0', or 'Air Mass Zero', refers to the spectral irradiance of sun light in the earth's outer atmosphere when the distance between the earth and sun is one astronomical unit (AU). | For the purposes of 3A001.e.4., 'AM0', or 'Air Mass Zero', refers to the spectral irradiance of sun light in the earth's outer atmosphere when the distance between the earth and sun is one astronomical unit (AU). |
| 3A002.a.6 技術註解 | 1.記錄器具平行匯流排結構者，〝連續資料產出量〞率為最高字元率乘以一個字中之位元數。<br>2.〝連續資料產出量〞係指儀器能夠記錄至磁碟或固態驅動記憶體，且維持其輸入數位資料率或數位轉換率，而不損失任何資訊之最快資料輸出率。 | 就 3A002.a.6.目的：<br>1.記錄器具平行匯流排結構者，〝連續資料產出量〞率為最高字元率乘以一個字中之位元數。<br>2.〝連續資料產出量〞係指儀器能夠記錄至磁碟或固態驅動記憶體，且維持其輸入數位資料率或數位轉換率，而不損失任何資訊之最快資料輸出率。 | 1. For recorders with a parallel bus architecture, the 'continuous throughput' rate is the highest word rate multiplied by the number of bits in a word.<br><br>2. 'Continuous throughput' is the fastest data rate the instrument can record to disk or solid-state drive memory without the loss of any information while sustaining the input digital data rate or digitizer conversion rate. | For the purposes of 3A002.a.6.:<br>1. For recorders with a parallel bus architecture, the 'continuous throughput' rate is the highest word rate multiplied by the number of bits in a word.<br><br>2. 'Continuous throughput' is the fastest data rate the instrument can record to disk or solid-state drive memory without the loss of any information while sustaining the input digital data rate or digitizer conversion rate. |
| 3A002.c.4 技術註解 | 1.〝即時頻寬〞指分析儀可持續傳送時域數據轉換為頻域結果之最大頻寬範圍，利用傅立葉或其他離散時間轉換，其處理每一個輸入時間點，無因間隙或窗口效應，使測量振幅低於實際訊號振幅超過 3dB。 | 就 3A002.c.4.a.目的，〝即時頻寬〞指分析儀可持續傳送時域數據轉換為頻域結果之最大頻寬範圍，利用傅立葉或其他離散時間轉換，其處理每一個輸入時間點，無因間隙或窗口效應，使測量振幅低於實際訊號振幅超 | 1. 'Real-time bandwidth' is the widest frequency range for which the analyser can continuously transform time-domain data entirely into frequency-domain results, using a Fourier or other discrete time transform that processes every incoming time point, without a | 1. For the purposes of 3A002.c.4.a., 'real-time bandwidth' is the widest frequency range for which the analyser can continuously transform time-domain data entirely into frequency-domain results, using a Fourier or other discrete time transform that processes every incoming time |

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| | 2. 3A002.c.4.b.1.中之發現率也被稱為攔截率或捕獲率。<br>3.就 3A002.c.4.b.1.目的，100%發現率的持續時間，即指定量測不確定度所需之最低訊號持續時間。<br>4. ˋ頻率遮罩觸發ˊ指訊號分析儀之一個機制，其觸發功能可選擇一個頻率範圍作為擷取頻寬的一個子集，而可忽略其他可能在同一擷取頻寬內之信號。一個ˋ頻率遮罩觸發ˊ可能有多於一個獨立限制的設置。 | 過 3dB。<br>2. 就 3A002.c.4.b.1.目的，發現率也被稱為攔截率或捕獲率。<br>3.就 3A002.c.4.b.1.目的，100%發現率的持續時間，即指定量測不確定度所需之最低訊號持續時間。<br>4. 就 3A002.c.4.b.2.目的，ˋ頻率遮罩觸發ˊ指訊號分析儀之一個機制，其觸發功能可選擇一個頻率範圍作為擷取頻寬的一個子集，而可忽略其他可能在同一擷取頻寬內之信號。一個ˋ頻率遮罩觸發ˊ可能有多於一個獨立限制的設置。 | reduction of measured amplitude of more than 3 dB below the actual signal amplitude caused by gaps or windowing effects, while outputting or displaying the transformed data.<br><br>2. Probability of discovery in 3A002.c.4.b.1. is also referred to as probability of intercept or probability of capture.<br><br>3. For the purposes of 3A002.c.4.b.1., the duration for 100 % probability of discovery is equivalent to the minimum signal duration necessary for the specified level measurement uncertainty.<br><br>4. A 'frequency mask trigger' is a mechanism where the trigger function is able to select a frequency range to be triggered on as a subset of the acquisition bandwidth while ignoring other signals that may also be present within the same acquisition bandwidth. A 'frequency mask trigger' may contain more than one independent set of limits. | point, without a reduction of measured amplitude of more than 3 dB below the actual signal amplitude caused by gaps or windowing effects, while outputting or displaying the transformed data.<br><br>2. For the purposes of 3A002.c.4.b.1., probability of discovery in 3A002.c.4.b.1. is also referred to as probability of intercept or probability of capture.<br><br>3. For the purposes of 3A002.c.4.b.1., the duration for 100 % probability of discovery is equivalent to the minimum signal duration necessary for the specified level measurement uncertainty.<br><br>4. For the purposes of 3A002.c.4.b.2., a 'frequency mask trigger' is a mechanism where the trigger function is able to select a frequency range to be triggered on as a subset of the acquisition bandwidth while ignoring other signals that may also be present within the same acquisition bandwidth. A 'frequency mask trigger' may contain more than one independent set of limits. |
| 3A002.d.4 技術註解 | 在 3A002.d.4.中，F 為以 Hz 為單位之操作頻率偏離值，而 f 為以 MHz 為單位之操作頻率； | 就 3A002.d.4.目的，F 為以 Hz 為單位之操作頻率偏離值，而 f 為以 MHz 為單位之操作頻率； | In 3A002.d.4., F is the offset from the operating frequency in Hz and f is the operating frequency in MHz; | For the purposes of 3A002.d.4., F is the offset from the operating frequency in Hz and f is the operating frequency in MHz; |

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| 3A002.d.5 技術註解 | ˋ射頻調變頻寬ˊ為一射頻(RF)頻寬,其由數位編碼基頻訊號調變至 RF 訊號所占用。其亦被稱作資訊頻寬或向量調變頻寬。I/Q 數位調變為用於生產向量調變 RF 輸出訊號之技術,其輸出訊號通常被指定為具有ˋ射頻調變頻寬ˊ。 | 就 3A002.d.5.目的,ˋ射頻調變頻寬ˊ為一射頻(RF)頻寬,其由數位編碼基頻訊號調變至 RF 訊號所占用。其亦被稱作資訊頻寬或向量調變頻寬。I/Q 數位調變為用於生產向量調變 RF 輸出訊號之技術,其輸出訊號通常被指定為具有ˋ射頻調變頻寬ˊ。 | 'RF modulation bandwidth' is the Radio Frequency (RF) bandwidth occupied by a digitally encoded baseband signal modulated onto an RF signal.  It is also referred to as information bandwidth or vector modulation bandwidth.  I/Q digital modulation is the technical method for producing a vector-modulated RF output signal, and that output signal is typically specified as having an 'RF modulation bandwidth'. | For the purposes of 3A002.d.5., 'RF modulation bandwidth' is the Radio Frequency (RF) bandwidth occupied by a digitally encoded baseband signal modulated onto an RF signal.  It is also referred to as information bandwidth or vector modulation bandwidth.  I/Q digital modulation is the technical method for producing a vector-modulated RF output signal, and that output signal is typically specified as having an 'RF modulation bandwidth'. |
| 3A002.d 技術註解 | 1. 任意波形及函數產生器之最大頻率計算,為以秒計算之取樣率除以係數 2.5。<br>2. 就 3A002.d.1.a.目的,ˋ脈衝持續時間ˊ定義為由脈衝波之前緣達50%之一點,至脈衝波後緣達 50%之一點兩者其時間間隔。 | 1. 就 3A002.d.目的,任意波形及函數產生器之最大頻率計算,為以秒計算之取樣率除以係數 2.5。<br>2. 就 3A002.d.1.a.目的,ˋ脈衝持續時間ˊ定義為由脈衝波之前緣達50%之一點,至脈衝波後緣達 50%之一點兩者其時間間隔。 | 1.　The maximum frequency of an arbitrary waveform or function generator is calculated by dividing the sample rate, in samples/second, by a factor of 2,5.<br>2.　For the purposes of 3A002.d.1.a, 'pulse duration' is defined as the time interval from the point on the leading edge that is 50 % of the pulse amplitude to the point on the trailing edge that is 50 % of the pulse amplitude. | 1.　For the purposes of 3A002.d., the maximum frequency of an arbitrary waveform or function generator is calculated by dividing the sample rate, in samples/second, by a factor of 2,5.<br>2.　For the purposes of 3A002.d.1.a, 'pulse duration' is defined as the time interval from the point on the leading edge that is 50 % of the pulse amplitude to the point on the trailing edge that is 50 % of the pulse amplitude. |
| 3A002.e.3 技術註解 | ˋ非線性向量量測ˊ為儀器其具有在設備驅動進入大訊號領域或線性失真範圍得到分析測試結果之能力。 | 就 3A002.e.3.目的,ˋ非線性向量量測ˊ為儀器其具有在設備驅動進入大訊號領域或線性失真範圍得到分析測試結果之能力。 | 'Nonlinear vector measurement functionality' is an instrument's ability to analyse the test results of devices driven into the large-signal domain or the non-linear distortion range. | For the purposes of 3A002.e.3., 'nonlinear vector measurement functionality' is an instrument's ability to analyse the test results of devices driven into the large-signal domain or the non-linear distortion range. |
| 3A002.h 技術註解 | 1. n 位元之解析度係對應於一個量子化的 2n 種狀態。<br>2. 輸出字的位元數相等於數位－類比轉換器之解析度,有效位元數(ENOB)不用於判讀 ADC 之解析度。<br>3. 對於非交錯式多頻道ˋ電子組 | 就 3A002.h.目的:<br>1. n 位元之解析度係對應於一個量子化的 2n 種狀態。<br>2. 輸出字的位元數相等於數位－類比轉換器之解析度,有效位元數(ENOB)不用於判讀 ADC 之解析度。 | 1.　A resolution of n bit corresponds to a quantisation of 2n levels.<br>2.　The resolution of the ADC is the number of bits of the digital output of the ADC that represents the measured analogue input. Effective Number of Bits (ENOB) is not used to determine the resolution of the ADC. | For the purposes of 3A002.h.:<br>1.　A resolution of n bit corresponds to a quantisation of 2n levels.<br>2.　The resolution of the ADC is the number of bits of the digital output of the ADC that represents the measured analogue input. Effective Number of Bits (ENOB) is not used to determine |

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| | 裝〞、模組或設備而言，〝取樣率〞非匯總結果，且〝取樣率〞是指任何單一頻道之最大輸出率。<br>4. 對於交錯式多頻道〝電子組裝〞、模組或設備而言，〝取樣率〞為匯總結果，〝取樣率〞為所有交錯頻道之最大輸出率組合。 | 3. 對於非交錯式多頻道〝電子組裝〞、模組或設備而言，〝取樣率〞非匯總結果，且〝取樣率〞是指任何單一頻道之最大輸出率。<br>4. 對於交錯式多頻道〝電子組裝〞、模組或設備而言，〝取樣率〞為匯總結果，〝取樣率〞為所有交錯頻道之最大輸出率組合。 | 3. For non-interleaved multiple-channel "electronic assemblies", modules, or equipment, the "sample rate" is not aggregated and the "sample rate" is the maximum rate of any single-channel.<br>4. For interleaved channels on multiple-channel "electronic assemblies", modules, or equipment, the "sample rates" are aggregated and the "sample rate" is the maximum combined total rate of all the interleaved channels. | the resolution of the ADC.<br>3. For non-interleaved multiple-channel "electronic assemblies", modules, or equipment, the "sample rate" is not aggregated and the "sample rate" is the maximum rate of any single-channel.<br>4. For interleaved channels on multiple-channel "electronic assemblies", modules, or equipment, the "sample rates" are aggregated and the "sample rate" is the maximum combined total rate of all the interleaved channels. |
| 3B001.e 技術註解 | 1. 3B001.e.所述〝半導體製程設備〞，為提供半導體實體加工生產之模組工具，其具有不同功能，如沉積、植入或熱處理等。<br>2. 3B001.e.所述〝序列多晶圓加工〞，為能同時在多個〝半導體製程設備〞上進行晶圓處理的能力；例如以自動裝載多腔中心晶圓處理系統上，將晶圓片從第一件工具轉移到第二件工具，再轉移到第三件工具。 | 1. 3B001.e.1.所述〝半導體製程設備〞，為提供半導體實體加工生產之模組工具，其具有不同功能，如沉積、植入或熱處理等。<br>2. 3B001.e.2.所述〝序列多晶圓加工〞，為能同時在多個〝半導體製程設備〞上進行晶圓處理的能力；例如以自動裝載多腔中心晶圓處理系統上，將晶圓片從第一件工具轉移到第二件工具，再轉移到第三件工具。 | 1. For the purpose of 3B001.e., 'semiconductor process tools' refers to modular tools that provide physical processes for semiconductor production that are functionally different, such as deposition, implant or thermal processing.<br>2. For the purpose of 3B001.e., 'sequential multiple wafer processing' means the capability to process each wafer in different 'semiconductor process tools', such as by transferring each wafer from one tool to a second tool and on to a third tool with the automatic loading multi-chamber central wafer handling systems. | 1. For the purpose of 3B001.e.1., 'semiconductor process tools' refers to modular tools that provide physical processes for semiconductor production that are functionally different, such as deposition, implant or thermal processing.<br>2. For the purpose of 3B001.e.2., 'sequential multiple wafer processing' means the capability to process each wafer in different 'semiconductor process tools', such as by transferring each wafer from one tool to a second tool and on to a third tool with the automatic loading multi-chamber central wafer handling systems. |
| 3B001.f.1.b 技術註解 | 〝最小可解析特徵尺寸〞(MRF)係由下列公式計算： | 就3B001.f.1.b.目的，〝最小可解析特徵尺寸〞(MRF)係由下列公式計算： | The 'Minimum Resolvable Feature size' (MRF) is calculated by the following formula: | For the purposes of 3B001.f.1.b., the 'Minimum Resolvable Feature size' (MRF) is calculated by the following formula: |

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| 3B001.j 技術註解 | ˋ極紫外線(EUV)ˊ指大於 5 nm 而小於 124 nm 的電磁譜波長。 | 就 3B001.j.目的：ˋ極紫外線(EUV)ˊ指大於 5 nm 而小於 124 nm 的電磁譜波長。 | 'Extreme Ultraviolet' ('EUV') refers to electromagnetic spectrum wavelengths greater than 5 nm and less than124 nm. | For the purposes of 3B001.j., 'Extreme Ultraviolet' ('EUV') refers to electromagnetic spectrum wavelengths greater than 5 nm and less than 124 nm. |
| 3D003 技術註解 | ˋ計算微影ˊ為利用電腦模型進行預測、校正、優化與驗證微影製程在一系列圖案、製程與系統條件下之成象性能。 | 就 3D003 目的，ˋ計算微影ˊ為利用電腦模型進行預測、校正、優化與驗證微影製程在一系列圖案、製程與系統條件下之成象性能。 | 'Computational lithography' is the use of computer modelling to predict, correct, optimise and verify imaging performance of the lithography process over a range of patterns, processes, and system conditions. | For the purposes of 3D003, 'computational lithography' is the use of computer modelling to predict, correct, optimise and verify imaging performance of the lithography process over a range of patterns, processes, and system conditions. |
| 3D006 技術註解 | 1. 〝電子計算機輔助設計〞（“ECAD”）是一類〝軟體〞工具，用於設計、分析、優化和驗證積體電路或印刷電路板的性能。<br>2. 〝暫存器轉移層次〞（“RTL”）是一種設計抽象模型，它根據硬體暫存器之間的數位訊號以及對這些訊號執行的邏輯操作來模擬同步數位電路。<br>3. 〝幾何數據庫標準 II〞（“GDSII”）是一種用於積體電路或積體電路佈局圖數據交換的數據庫文件格式。 | 就 3D006 目的：<br>1. 〝電子計算機輔助設計〞（“ECAD”）是一類〝軟體〞工具，用於設計、分析、優化和驗證積體電路或印刷電路板的性能。<br>2. 〝暫存器轉移層次〞（“RTL”）是一種設計抽象模型，它根據硬體暫存器之間的數位訊號以及對這些訊號執行的邏輯操作來模擬同步數位電路。<br>3. 〝幾何數據庫標準 II〞（“GDSII”）是一種用於積體電路或積體電路佈局圖數據交換的數據庫文件格式。 | 1.'Electronic Computer-Aided Design' ('ECAD') is a category of "software" tools used for designing, analysing, optimising, and validating the performance of integrated circuit or printed circuit board.<br><br>2.'Register Transfer Level' ('RTL') is a design abstraction which models a synchronous digital circuit in terms of the flow of digital signals between hardware registers, and the logical operations performed on those signals.<br><br>3.'Geometrical Database Standard II' ('GDSII') is a database file format for data exchange of integrated circuit or integrated circuit layout artwork. | For the purposes of 3D006:<br>1.'Electronic Computer-Aided Design' ('ECAD') is a category of "software" tools used for designing, analysing, optimising, and validating the performance of integrated circuit or printed circuit board.<br><br>2.'Register Transfer Level' ('RTL') is a design abstraction which models a synchronous digital circuit in terms of the flow of digital signals between hardware registers, and the logical operations performed on those signals.<br><br>3.'Geometrical Database Standard II' ('GDSII') is a database file format for data exchange of integrated circuit or integrated circuit layout artwork. |
| 3E001 註解 3 技術註解 | ˋ製程設計套件ˊ（ˋPDKsˊ）為半導體製造商所提供之軟體工具，用以確保必要的設計作法與規則，以能在特定半導體製程中根據技術和製造限制，成功的生產積體電路（每個半導體製程都有其特定的ˋPDKˊ）。 | 就 3E001 Note 3 目的，ˋ製程設計套件ˊ（ˋPDKsˊ）為半導體製造商所提供之軟體工具，用以確保必要的設計作法與規則，以能在特定半導體製程中根據技術和製造限制，成功的生產積體電路（每個半導體製程都有其 | A 'Process Design Kit' ('PDK') is a software tool provided by a semiconductor manufacturer to ensure that the required design practices and rules are taken into account in order to successfully produce a specific integrated circuit design in a specific semiconductor process, in accordance | For the purposes of 3E001Note 3, a 'Process Design Kit' ('PDK') is a software tool provided by a semiconductor manufacturer to ensure that the required design practices and rules are taken into account in order to successfully produce a specific integrated circuit design in a specific |

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| | | 特定的〝PDK〞)。 | with technological and manufacturing constraints (each semiconductor manufacturing process has its particular 'PDK'). | semiconductor process, in accordance with technological and manufacturing constraints (each semiconductor manufacturing process has its particular 'PDK'). |
| 3E002.a 技術註解 | 〝向量處理器單元〞是一個處理元件具有內建指令,可同時執行多重〝浮點〞向量(32 位元或以上之一維陣列)計算,並具有至少一個向量運算邏輯單元及至少有 32 個元件之向量暫存器。 | 就 3E002.a.目的,〝向量處理器單元〞是一個處理元件具有內建指令,可同時執行多重〝浮點〞向量(32 位元或以上之一維陣列)計算,並具有至少一個向量運算邏輯單元及至少有 32 個元件之向量暫存器。 | A 'vector processor unit' is a processor element with built-in instructions that perform multiple calculations on 'floating-point' vectors (one-dimensional arrays of 32-bit or larger numbers) simultaneously, having at least one vector arithmetic logic unit and vector registers of at least 32 elements each. | For the purposes of 3E002.a., a 'vector processor unit' is a processor element with built-in instructions that perform multiple calculations on 'floating-point' vectors (one-dimensional arrays of 32-bit or larger numbers) simultaneously, having at least one vector arithmetic logic unit and vector registers of at least 32 elements each. |
| 第 4 類註解 2 技術註解 | 〝主儲存體〞指由中央處理器快速存取之主要資料或指令儲存裝置。其由〝數位電腦〞內部儲存裝置及其分級延伸部分所組成,如高速緩衝儲存裝置或非序列存取延伸儲存裝置。 | 就 Note 2 目的,〝主儲存體〞指由中央處理器快速存取之主要資料或指令儲存裝置。其由〝數位電腦〞內部儲存裝置及其分級延伸部分所組成,如高速緩衝儲存裝置或非序列存取延伸儲存裝置。 | 'Main storage' is the primary storage for data or instructions for rapid access by a central processing unit. It consists of the internal storage of a "digital computer" and any hierarchical extension thereto, such as cache storage or non-sequentially accessed extended storage. | For the purposes of Note 2, 'main storage' is the primary storage for data or instructions for rapid access by a central processing unit. It consists of the internal storage of a "digital computer" and any hierarchical extension thereto, such as cache storage or non-sequentially accessed extended storage. |
| 4A004 技術註解 | 1.〝脈動陣列電腦〞指可由使用者在邏輯閘層次機動控制資料流通與修改之電腦。<br>2.〝類神經電腦〞指設計或修改以模仿神經細胞或一群神經細胞之行為之計算裝置,即此計算裝置以其硬體性能區別其特色,而此硬體可依據以往資料調整多重計算組件之重量與其互連數目。<br>3.〝光學電腦〞指設計或修改以使用光呈現資料之電腦,其邏輯運算元件以直接耦合光學裝置為基礎。 | 1. 就 4A004.a.目的,〝脈動陣列電腦〞指可由使用者在邏輯閘層次機動控制資料流通與修改之電腦。<br>2. 就 4A004.b.目的,〝類神經電腦〞指設計或修改以模仿神經細胞或一群神經細胞之行為之計算裝置,即此計算裝置以其硬體性能區別其特色,而此硬體可依據以往資料調整多重計算組件之重量與其互連數目。<br>3. 就 4A004.c.目的,〝光學電腦〞指設計或修改以使用光呈現資料之電腦,其邏輯運算元件以直接耦合光學 | 1. 'Systolic array computers' are computers where the flow and modification of the data is dynamically controllable at the logic gate level by the user.<br><br>2. 'Neural computers' are computational devices designed or modified to mimic the behaviour of a neuron or a collection of neurons, i.e., computational devices which are distinguished by their hardware capability to modulate the weights and numbers of the interconnections of a multiplicity of computational components based on previous data. | 1. For the purposes of 4A004.a., 'systolic array computers' are computers where the flow and modification of the data is dynamically controllable at the logic gate level by the user.<br><br>2. For the purposes of 4A004.b., 'neural computers' are computational devices designed or modified to mimic the behaviour of a neuron or a collection of neurons, i.e., computational devices which are distinguished by their hardware capability to modulate the weights and numbers of the interconnections of a multiplicity of computational components based on |

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| | | 裝置為基礎。 | 3. 'Optical computers' are computers designed or modified to use light to represent data and whose computational logic elements are based on directly coupled optical devices. | previous data.<br><br>3. For the purposes of 4A004.c., 'optical computers' are computers designed or modified to use light to represent data and whose computational logic elements are based on directly coupled optical devices. |
| 4D001.b.1 | 1. 〝數位電腦〞具有〝調整尖峰效能〞 (〝APP〞)超過15加權兆浮點運算(WT)者; | 1. 〝數位電腦〞具有〝調整尖峰效能〞 (〝APP〞)超過24加權兆浮點運算(WT)者; | 1. "Digital computers" having an "Adjusted Peak Performance" ("APP") exceeding 15 Weighted TeraFLOPS (WT); | 1. "Digital computers" having an "Adjusted Peak Performance" ("APP") exceeding 24 Weighted TeraFLOPS (WT); |
| 4E001 | 無 | 〝技術〞如下: | - | " Technology " as follows: |
| 4E001.b.1 | 1. 〝數位電腦〞具有〝調整尖峰效能〞 (〝APP〞)超過15加權兆浮點運算(WT)者; | 1. 〝數位電腦〞具有〝調整尖峰效能〞 (〝APP〞)超過24加權兆浮點運算(WT)者; | 1. "Digital computers" having an "Adjusted Peak Performance" ("APP") exceeding 15 Weighted TeraFLOPS (WT); | 1. "Digital computers" having an "Adjusted Peak Performance" ("APP") exceeding 24 Weighted TeraFLOPS (WT); |
| 5A001.b.5 技術註解 | ˋ頻道切換時間´指由一個接收頻率至另一個頻率的時間(即延遲),其在 ±0.05 % 或以內到達指定接收頻率。項目具與其中心頻率小於 ±0.05 %之特定頻率範圍,被定義為無能力進行頻道頻率切換。 | 就 5A001.b.5.b.目的,ˋ頻道切換時間´指由一個接收頻率至另一個頻率的時間(即延遲),其在 ±0.05 % 或以內到達指定接收頻率。項目具與其中心頻率小於 ±0.05 %之特定頻率範圍,被定義為無能力進行頻道頻率切換。 | 'Channel switching time' means the time (i.e., delay) to change from one receiving frequency to another, to arrive at or within ± 0,05 % of the final specified receiving frequency. Items having a specified frequency range of less than ± 0,05 % around their centre frequency are defined to be incapable of channel frequency switching. | For the purposes of 5A001.b.5.b., 'channel switching time' means the time (i.e., delay) to change from one receiving frequency to another, to arrive at or within ± 0,05 % of the final specified receiving frequency. Items having a specified frequency range of less than ± 0,05 % around their centre frequency are defined to be incapable of channel frequency switching. |
| 5A001.c 技術註解 | ˋ驗證測試´:線上或離線生產篩選測試,動態施予特定之拉張應力於長度 0.5 至 3 m 之光纖上,其運行率在 2 至 5 m/s 下,通過直徑大約 150 mm | 就 5A001.c.目的,ˋ驗證測試´:線上或離線生產篩選測試,動態施予特定之拉張應力於長度 0.5 至 3 m 之光纖上,其運行率在 2 至 5 m/s 下,通 | 'Proof Test': on-line or off-line production screen testing that dynamically applies a prescribed tensile stress over a 0,5 to 3 m length of fibre at a running rate of 2 to 5 m/s while passing | For the purposes of 5A001.c., 'proof Test': on-line or off-line production screen testing that dynamically applies a prescribed tensile stress over a 0,5 to 3 m length of fibre at a running rate of 2 to 5 m/s while passing between capstans |

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| | 的絞盤之間。測試之周圍溫度為 293 k (20 °C)，相對濕度為 40 ％。可使用等效國家標準於此驗證測試。 | 過直徑大約 150 mm 的絞盤之間。測試之周圍溫度為 293 k (20 °C)，相對濕度為 40 ％。可使用等效國家標準於此驗證測試。 | between capstans approximately 150 mm in diameter. The ambient temperature is a nominal 293 K (20 °C) and relative humidity 40 %. Equivalent national standards may be used for executing the proof test. | approximately 150 mm in diameter. The ambient temperature is a nominal 293 K (20 °C) and relative humidity 40 %. Equivalent national standards may be used for executing the proof test. |
| 5A001.g 技術註解 | 非雷達發射器可能包括商用無線電、電視或蜂巢式電訊基地台。 | 就 5A001.g.目的，非雷達發射器可能包括商用無線電、電視或蜂巢式電訊基地台。 | Non-radar transmitters may include commercial radio, television or cellular telecommunications base stations. | For the purposes of 5A001.g., non-radar transmitters may include commercial radio, television or cellular telecommunications base stations. |
| 5A002.a 註解 a.1.b.1 技術註解 | 〝個人資料〞指包括特定人或機構之所有資料，例如存款金額與進行驗證的必要資料。 | 就 5A002.a. 註解 2 a.1.b.1.目的，〝個人資料〞指包括特定人或機構之所有資料，例如存款金額與進行驗證的必要資料。 | 'Personal data' includes any data specific to a particular person or entity, such as the amount of money stored and data necessary for "authentication". | For the purposes of 5A002.a. Note a.1.b.1., 'personal data' includes any data specific to a particular person or entity, such as the amount of money stored and data necessary for "authentication". |
| 5A002.a 註解 a.1.b.2 技術註解 | 〝讀卡機/寫入機〞包括透過網路以智慧卡或電子讀取式證件進行傳遞之設備。 | 就 5A002.a. 註解 2 a.1.b.2.目的，〝讀卡機/寫入機〞包括透過網路以智慧卡或電子讀取式證件進行傳遞之設備。 | 'Readers/writers' include equipment that communicates with smart cards or electronically readable documents through a network. | For the purposes of 5A002.a. Note a.1.b.2., 'readers/writers' include equipment that communicates with smart cards or electronically readable documents through a network. |
| 5A002.a 註解 b 技術註解 | 〝貨幣交易〞包括費用的收取與結算，或信貸功能。 | 就 5A002.a.註解 2.b.目的，〝貨幣交易〞包括費用的收取與結算，或信貸功能。 | 'Money transactions' includes the collection and settlement of fares or credit functions. | For the purposes of 5A002.a. Note b., 'money transactions' includes the collection and settlement of fares or credit functions. |
| 5A002.a 註解 j 技術註解 | 1. 〝互聯民用工業應用〞指在〝資訊安全〞以外與消費或民間工業應用的網路連線、數據通訊、通用網路連結或計算。<br>2. 〝非任意數據〞指由感測器或計量所得數據，其直接相關穩定性、性能或物理測量系統(如溫度、壓力、流量、質量、體積、電壓、所在位置等)，設備使用者無法更改的內容。 | 1. 就 5A002.a. 註解 2 j.目的，〝互聯民用工業應用〞指在〝資訊安全〞以外與消費或民間工業應用的網路連線、數據通訊、通用網路連結或計算。<br>2. 就 5A002.a. 註解 2 j.1.a.1.目的，〝非任意數據〞指由感測器或計量所得數據，其直接相關穩定性、性能或物理測量系統(如溫度、壓力、流量、質量、體積、電壓、所在位置等)，設 | 1. 'Connected civil industry application' means a network connected consumer or civil industry application other than "information security", digital communication, general purpose networking or computing.<br><br>2 . 'Non-arbitrary data' means sensor or metering data directly related to the stability, performance or physical measurement of a system (e.g., | 1.For the purposes of 5A002.a. Note j., 'connected civil industry application' means a network connected consumer or civil industry application other than "information security", digital communication, general purpose networking or computing.<br><br>2 .For the purposes of 5A002.a. Note j.1.a.1., 'non-arbitrary data' means sensor or metering data directly related to the stability, performance or physical |

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| | | 備使用者無法更改的內容。 | temperature, pressure, flow rate, mass, volume, voltage, physical location etc.), that cannot be changed by the user of the device. | measurement of a system (e.g., temperature, pressure, flow rate, mass, volume, voltage, physical location etc.), that cannot be changed by the user of the device. |
| 5A002.b 技術註解 | 〝密碼啟用〞是指為以下任一目的而設計或修改的項目： | 就 5A002.b.目的，〝密碼啟用〞是指為以下任一目的而設計或修改的項目： | A 'cryptographic activation token' is an item designed or modified for any of the following: | For the purposes of 5A002.b., a 'cryptographic activation token' is an item designed or modified for any of the following: |
| 5A002.c 技術註解 | 〝量子加密技術〞亦稱為量子金鑰分配(QKD)。 | 就 5A002.c.目的，〝量子加密技術〞亦稱為量子金鑰分配(QKD)。 | "Quantum cryptography" is also known as Quantum Key Distribution (QKD). | For the purposes of 5A002.c., "quantum cryptography" is also known as Quantum Key Distribution (QKD). |
| 5A004.a 技術註解 | 〝密碼分析功能〞指設計用於破解加密機制以便得出機密訊息或敏感資料，包括明碼、密碼或加密金鑰。 | 就 5A004.a.目的，〝密碼分析功能〞指設計用於破解加密機制以便得出機密訊息或敏感資料，包括明碼、密碼或加密金鑰。 | 'Cryptanalytic functions' are functions designed to defeat cryptographic mechanisms in order to derive confidential variables or sensitive data, including clear text, passwords or cryptographic keys. | For the purposes of 5A004.a.,'cryptanalytic functions' are functions designed to defeat cryptographic mechanisms in order to derive confidential variables or sensitive data, including clear text, passwords or cryptographic keys. |
| 5A004.b 技術註解 | 由計算或通信裝置中〝提取原始資料〞，指由設備的儲存媒體(例如：RAM、快閃記憶體或硬碟)中檢索二進制數據，而無需設備操作系統或檔案系統進行解釋。 | 就 5A004.b.1.目的，由計算或通信裝置中〝提取原始資料〞，指由設備的儲存媒體(例如：RAM、快閃記憶體或硬碟)中檢索二進制數據，而無需設備操作系統或檔案系統進行解釋。 | 'Extract raw data' from a computing or communications device means to retrieve binary data from a storage medium (e.g., RAM, flash or hard disk) of the device without interpretation by the device's operating system or filesystem. | For the purposes of 5A004.b.1., 'extract raw data' from a computing or communications device means to retrieve binary data from a storage medium (e.g., RAM, flash or hard disk) of the device without interpretation by the device's operating system or filesystem. |
| 6A001.a.1.a.1 技術註解 | 1. 〝探測解析度〞是將探測帶寬度(度數)除以每個探測帶最高探測次數。<br>2. 〝強化〞包括透過外部方式來補償能力。 | 1. 就 6A001.a.1.a.1.c.目的，〝探測解析度〞是將探測帶寬度(度數)除以每個探測帶最高探測次數。<br>2. 就 6A001.a.1.a.目的，〝強化〞包括透過外部方式來補償能力。 | 1.'Sounding resolution' is the swath width (degrees) divided by the maximum number of soundings per swath.<br><br>2. 'Enhancement' includes the ability to compensate by external means. | 1.For the purposes of 6A001.a.1.a.1.c., 'sounding resolution' is the swath width (degrees) divided by the maximum number of soundings per swath.<br><br>2. For the purposes of 6A001.a.1.a., 'enhancement' includes the ability to compensate by external means. |

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|---|---|---|---|---|
| 6A001.a.1.a.2 技術註解 | 聲學感測器由 6A001.a.1.a.2.所述之設備以壓力等級判定深度等級。 | 就 6A001.a.1.a.2.目的，聲學感測器由 6A001.a.1.a.2.所述之設備以壓力等級判定深度等級。 | The acoustic sensor pressure rating determines the depth rating of the equipment specified in 6A001.a.1.a.2. | For the purposes of 6A001.a.1.a.2., the acoustic sensor pressure rating determines the depth rating. |
| 6A001.a.1.a.2.a 技術註解 | ˋ探測速率ˊ指產品在感測器操作之最高速度(m/s)乘以每個探測帶之最高探測次數，假設其為 100 % 覆蓋率。對於產生 2 個方向探測系統(3D 聲納)，其各個方向都應使用最大ˋ探測速率ˊ。 | 就 6A001.a.1.a.2.a.2.目的，ˋ探測速率ˊ指產品在感測器操作之最高速度(m/s)乘以每個探測帶之最高探測次數，假設其為 100 % 覆蓋率。對於產生 2 個方向探測系統(3D 聲納)，其各個方向都應使用最大ˋ探測速率ˊ。 | 'Sounding rate' is the product of the maximum speed (m/s) at which the sensor can operate and the maximum number of soundings per swath assuming 100 % coverage. For systems that produce soundings in two directions (3D sonars), the maximum of the 'sounding rate' in either direction should be used. | For the purposes of 6A001.a.1.a.2.a.2.,'sounding rate' is the product of the maximum speed (m/s) at which the sensor can operate and the maximum number of soundings per swath assuming 100 % coverage. For systems that produce soundings in two directions (3D sonars), the maximum of the 'sounding rate' in either direction should be used. |
| 6A001.a.1.a.3 技術註解 | 1. ˋ面積覆蓋率ˊ (m2/s)為 2 倍於產品聲納範圍(m)乘以感測器操作之最高速度(m/s)，在聲納可操作範圍內。<br>2. ˋ沿軌解析度ˊ (cm)，僅適用於 SSS，為產品方位角(水平)的波束寬(度數)乘以聲納範圍(公尺)再乘以 0.873。<br>3.ˋ跨軌解析度ˊ (cm)為 75 除以訊號頻寬(kHz)。 | 就 6A001.a.1.a.3.目的:<br>1. ˋ面積覆蓋率ˊ (m2/s)為 2 倍於產品聲納範圍(m)乘以感測器操作之最高速度(m/s)，在聲納可操作範圍內。<br>2. ˋ沿軌解析度ˊ (cm)，僅適用於 SSS，為產品方位角(水平)的波束寬(度數)乘以聲納範圍(公尺)再乘以 0.873。<br>3.ˋ跨軌解析度ˊ (cm)為 75 除以訊號頻寬(kHz)。 | 1.  'Area coverage rate' (m2/s) is twice the product of the sonar range (m) and the maximum speed (m/s) at which the sensor can operate at that range.<br><br>2.  'Along track resolution' (cm), for SSS only, is the product of azimuth (horizontal) beamwidth (degrees) and sonar range (m) and 0,873.<br><br>3.  'Across track resolution' (cm) is 75 divided by the signal bandwidth (kHz). | For the purposes of 6A001.a.1.a.3.:<br><br>1.  'Area coverage rate' (m2/s) is twice the product of the sonar range (m) and the maximum speed (m/s) at which the sensor can operate at that range.<br><br>2.  'Along track resolution' (cm), for SSS only, is the product of azimuth (horizontal) beamwidth (degrees) and sonar range (m) and 0,873.<br><br>3.  'Across track resolution' (cm) is 75 divided by the signal bandwidth (kHz). |
| 6A001.a.1.c.1 技術註解 | ˋ自由場訊源位準(SLRMS)ˊ定義為沿聲波投射器最大響應軸線與最遠區域，其可由發送電壓響應(TVR)獲得如下公式：SLRMS= (TVR + 20logVRMS) dB(在 1 公尺深度下 1μPa 為參考基準)，其中 SLRMS 為訊源位準，TVR 為發射電壓響應，VRMS | 就 6A001.a.1.c.1.目的，ˋ自由場訊源位準(SLRMS)ˊ定義為沿聲波投射器最大響應軸線與最遠區域，其可由發送電壓響應(TVR)獲得如下公式：SLRMS= (TVR + 20logVRMS) dB(在 1 公尺深度下 1μ Pa 為參考基準)，其中 SLRMS 為訊源位準，TVR 為發 | The 'free-field Source Level (SLRMS)' is defined along the maximum response axis and in the far field of the acoustic projector. It can be obtained from the Transmitting Voltage Response using the following equation: SLRMS = (TVR + 20log VRMS) dB (ref 1μPa at 1 m), where SLRMS is the source level, TVR is the | For the purposes of 6A001.a.1.c.1., the 'free-field Source Level (SLRMS)' is defined along the maximum response axis and in the far field of the acoustic projector. It can be obtained from the Transmitting Voltage Response using the following equation: SLRMS = (TVR + 20log VRMS) dB (ref 1μPa at 1 m), where SLRMS is the source level, TVR |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| | 為聲波投射器之驅動電壓。 | 射電壓響應,VRMS 為聲波投射器之驅動電壓。 | Transmitting Voltage Response and VRMS is the Driving Voltage of the Projector. | is the Transmitting Voltage Response and VRMS is the Driving Voltage of the Projector. |
| 6A001.a.2.a 技術註解 | 1. 水中聽音器包含1個或以上感測元件產生單一聲音輸出頻道。其包含多類元件者,可被稱為水中聽音器組合。<br>2. 就 6A001.a.2.a.而言,水下聲能轉換器設計用於操作被動接收器者即為水中聽音器。 | 就 6A001.a.2.a.目的:<br>1. 水中聽音器包含1個或以上感測元件產生單一聲音輸出頻道。其包含多類元件者,可被稱為水中聽音器組合。<br>2. 就 6A001.a.2.a.而言,水下聲能轉換器設計用於操作被動接收器者即為水中聽音器。 | 1.   Hydrophones consist of one or more sensing elements producing a single acoustic output channel. Those that contain multiple elements can be referred to as a hydrophone group.<br>2.   Underwater acoustic transducers designed to operate as passive receivers are hydrophones. | For the purposes of 6A001.a.2.a.:<br>1.   Hydrophones consist of one or more sensing elements producing a single acoustic output channel. Those that contain multiple elements can be referred to as a hydrophone group.<br>2.   Underwater acoustic transducers designed to operate as passive receivers are hydrophones. |
| 6A001.a.2.a.3 技術註解 | 1. ˋ壓電聚合膜ˊ之感測元件是由伸展及依附在一個框架或線軸上之極化聚合膜組成。<br>2. ˋ可撓式壓電複合材料ˊ之感測元件是由壓電陶瓷粒子或電絕緣之纖維、聲音可穿透之橡膠、聚合物或環氧樹脂化合物所組成,而該化合物為感測元件之一部分。<br>3. ˋ水中聽音器之靈敏度ˊ係指,將沒有前放大器的水中聽音器置於壓力 1μPa 均方根值之平面聲場中測量時,以輸出電壓之均方根(rms)值對 1 V rms 參考值之比值,取以 10 為底數之對數值後,再乘以 20 而得。例如:一個-160 dB 的水中聽音器會產生 10-8 伏輸出 | 1.就 6A001.a.2.a.3.b.目的,ˋ壓電聚合膜ˊ之感測元件是由伸展及依附在一個框架或線軸上之極化聚合膜組成。<br>2. 就 6A001.a.2.a.3.c.目的,ˋ可撓式壓電複合材料ˊ之感測元件是由壓電陶瓷粒子或電絕緣之纖維、聲音可穿透之橡膠、聚合物或環氧樹脂化合物所組成,而該化合物為感測元件之一部分。<br>3. 就 6A001.a.2.a.目的,ˋ水中聽音器之靈敏度ˊ係指,將沒有前放大器的水中聽音器置於壓力 1μPa 均方根值之平面聲場中測量時,以輸出電壓之均方根(rms)值對 1 V rms 參考值之比值,取以 10 為底數之對數值後,再 | 1.   'Piezoelectric polymer film' sensing elements consist of polarised polymer film that is stretched over and attached to a supporting frame or spool (mandrel).<br>2.   'Flexible piezoelectric composite' sensing elements consist of piezoelectric ceramic particles or fibres combined with an electrically insulating, acoustically transparent rubber, polymer or epoxy compound, where the compound is an integral part of the sensing elements.<br>3.   'Hydrophone sensitivity' is defined as twenty times the logarithm to the base 10 of the ratio of rms output voltage to a 1 V rms reference, when the hydrophone sensor, without a pre-amplifier, is placed in a plane wave acoustic field with an rms pressure of 1 µPa. For example, a hydrophone of – 160 dB (reference 1 | 1.   For the purposes of 6A001.a.2.a.3.b., 'piezoelectric polymer film' sensing elements consist of polarised polymer film that is stretched over and attached to a supporting frame or spool (mandrel).<br>2.   For the purposes of 6A001.a.2.a.3.c., 'flexible piezoelectric composite' sensing elements consist of piezoelectric ceramic particles or fibres combined with an electrically insulating, acoustically transparent rubber, polymer or epoxy compound, where the compound is an integral part of the sensing elements.<br>3.   For the purposes of 6A001.a.2.a., 'hydrophone sensitivity' is defined as twenty times the logarithm to the base 10 of the ratio of rms output voltage to a 1 V rms reference, when the hydrophone sensor, without a pre-amplifier, is placed in a plane wave acoustic field |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| | 電壓(其參考值為 1V 每 1μPa)，而一個-180 dB 靈敏度的水中聽音器僅輸出 10-9 伏電壓。因此，在此音場強度下的-160 dB 比-180 dB 具有較佳靈敏度。 | 乘以 20 而得。例如：一個-160 dB 的水中聽音器會產生 10-8 伏輸出電壓(其參考值為 1V 每 1μPa)，而一個-180 dB 靈敏度的水中聽音器僅輸出 10-9 伏電壓。因此，在此音場強度下的-160 dB 比-180 dB 具有較佳靈敏度。 | V per μPa) would yield an output voltage of 10– 8 V in such a field, while one of – 180 dB sensitivity would yield only 10– 9 V output. Thus, – 160 dB is better than – 180 dB | with an rms pressure of 1 μPa. For example, a hydrophone of – 160 dB (reference 1 V per μPa) would yield an output voltage of 10– 8 V in such a field, while one of – 180 dB sensitivity would yield only 10– 9 V output. Thus, – 160 dB is better than – 180 dB. |
| 6A002.a.2.b 技術註解 | 水中聽音器陣列包由許多水中聽音器組成，其提供多個聲音輸出頻道。 | 就 6A001.a.2.b.目的，水中聽音器陣列包由許多水中聽音器組成，其提供多個聲音輸出頻道。 | Hydrophone arrays consist of a number of hydrophones providing multiple acoustic output channels. | For the purposes of 6A001.a.2.b., hydrophone arrays consist of a number of hydrophones providing multiple acoustic output channels. |
| 6A002.a.2.b.2 技術註解 | 6A001.a.2.b.1.及 6A001.a.2.b.2.所述ˋ可修改ˊ係指，容許線路或連接線變動的配置方式，以更改水中聽音器群組間距或操作之水深極限，這些配置方式包括：線路數目中有超過 10 % 的備用線路，水中聽音器群組間距調整區塊或可調式內部水深極限裝置，或可控制一組以上之水中聽音器群組。 | 就 6A001.a.2.b.2.目的，在 6A001.a.2.b.1.和 2.中的ˋ可修改ˊ係指，容許線路或連接線變動的配置方式，以更改水中聽音器群組間距或操作之水深極限，這些配置方式包括：線路數目中有超過 10 % 的備用線路，水中聽音器群組間距調整區塊或可調式內部水深極限裝置，或可控制一組以上之水中聽音器群組。 | 'Able to be modified' in 6A001.a.2.b.1. and 2. means having provisions to allow a change of the wiring or interconnections to alter hydrophone group spacing or operating depth limits. These provisions are: spare wiring exceeding 10 % of the number of wires, hydrophone group spacing adjustment blocks or internal depth limiting devices that are adjustable or that control more than one hydrophone group. | For the purposes of 6A001.a.2.b.2., 'able to be modified' in 6A001.a.2.b.1. and 2. means having provisions to allow a change of the wiring or interconnections to alter hydrophone group spacing or operating depth limits. These provisions are: spare wiring exceeding 10 % of the number of wires, hydrophone group spacing adjustment blocks or internal depth limiting devices that are adjustable or that control more than one hydrophone group. |
| 6A001.a.2.g 技術註解 | 1.基於加速度之水中聲學感測器亦被稱為向量感測器。<br>2.ˋ加速度靈敏度ˊ定義為以 1 V 均方根為基準，輸出電壓均方根取以 10 為底數之對數值後乘以 20，當水中聲學感測器不具前置放大器，將其置於一平面波音場，在 1g 均方根加速度(即 9.81 m/s2)之下。 | 1.就 6A001.a.2.g.目的，基於加速度之水中聲學感測器亦被稱為向量感測器。<br>2.就 6A001.a.2.g.2.目的，ˋ加速度靈敏度ˊ定義為以 1 V 均方根為基準，輸出電壓均方根取以 10 為底數之對數值後乘以 20，當水中聲學感測器不具前置放大器，將其置於一平面波音場，在 1g 均方根加速度(即 9.81 m/s2) | 1. Accelerometer-based hydro-acoustic sensors are also known as vector sensors.<br><br>2. 'Acceleration sensitivity' is defined as twenty times the logarithm to the base 10 of the ratio of rms output voltage to a 1 V rms reference, when the hydro-acoustic sensor, without a preamplifier, is placed in a plane wave acoustic field with an rms acceleration of 1 g (i.e., 9,81 m/s2). | 1.For the purposes of 6A001.a.2.g., accelerometer-based hydro-acoustic sensors are also known as vector sensors.<br><br>2.For the purposes of 6A001.a.2.g.2., 'acceleration sensitivity' is defined as twenty times the logarithm to the base 10 of the ratio of rms output voltage to a 1 V rms reference, when the hydro-acoustic sensor, without a preamplifier, is placed in a plane wave acoustic field with an rms acceleration |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| | | 之下。 | | of 1 g (i.e., 9,81 m/s2). |
| 6A002.a.2 技術註解 | 〝電子倍增〞為電子影像增強形式，定義為由碰撞電離子增益程序導致電子載體產生。〝電子倍增〞感測器可採取的形式為影像增強管、固態偵測器或〝焦面陣列〞。 | 就 6A002.a.2.目的，〝電子倍增〞為電子影像增強形式，定義為由碰撞電離子增益程序導致電子載體產生。〝電子倍增〞感測器可採取的形式為影像增強管、固態偵測器或〝焦面陣列〞。 | 'Charge multiplication' is a form of electronic image amplification and is defined as the generation of charge carriers as a result of an impact ionization gain process. 'Charge multiplication' sensors may take the form of an image intensifier tube, solid state detector or "focal plane array". | For the purposes of 6A002.a.2., 'charge multiplication' is a form of electronic image amplification and is defined as the generation of charge carriers as a result of an impact ionization gain process. 'Charge multiplication' sensors may take the form of an image intensifier tube, solid state detector or "focal plane array". |
| 6A002.a.3 技術註解 | 線性或 2 維之多元件偵測陣列稱為〝焦面陣列〞; | 就 6A002.a.3.目的，線性或 2 維之多元件偵測陣列稱為〝焦面陣列〞; | Linear or two-dimensional multi-element detector arrays are referred to as "focal plane arrays"; | For the purposes of 6A002.a.3., linear or two-dimensional multi-element detector arrays are referred to as "focal plane arrays"; |
| 6A002.a.3 註解 2.c.2.a | 反應限制機制與偵測器元件整合為一體，指設計為不可移除或改裝，除非偵測器無法正常操作。 | 就 6A002.a.3. 註解 2.c.2.a.目的，反應限制機制與偵測器元件整合為一體，指設計為不可移除或改裝，除非偵測器無法正常操作。 | A response limiting mechanism integral to the detector element is designed not to be removed or modified without rendering the detector inoperable. | For the purposes of 6A002.a.3. Note 2.c.2.a., a response limiting mechanism integral to the detector element is designed not to be removed or modified without rendering the detector inoperable. |
| 6A002.c 技術註解 | 〝直視〞意指指於可見光譜或紅外線光譜下操作之影像設備，無需將影像轉換成電視顯示器使用之電子訊號，即可呈現可見影像予觀測者，但無法將該影像以照相、電子或其他方法記錄或儲存。 | 就 6A002.c.目的，〝直視〞意指指於可見光譜或紅外線光譜下操作之影像設備，無需將影像轉換成電視顯示器使用之電子訊號，即可呈現可見影像予觀測者，但無法將該影像以照相、電子或其他方法記錄或儲存。 | 'Direct view' refers to imaging equipment that presents a visual image to a human observer without converting the image into an electronic signal for television display, and that cannot record or store the image photographically, electronically or by any other means. | For the purposes of 6A002.c., 'direct view' refers to imaging equipment that presents a visual image to a human observer without converting the image into an electronic signal for television display, and that cannot record or store the image photographically, electronically or by any other means. |
| 6A002.f 技術註解 | 〝讀出積體電路〞(〝ROIC〞)指積體電路設計用於支持或結合〝焦面陣列〞(〝FPA〞)，其使用於讀出(即擷取與暫存)探測元件所產生的訊號，最 | 就 6A002.f.目的，〝讀出積體電路〞(〝ROIC〞)指積體電路設計用於支持或結合〝焦面陣列〞(〝FPA〞)，其使用於讀出(即擷取與暫存)探測元件 | A 'Read-Out Integrated Circuit' ('ROIC') is an integrated circuit designed to underlie or be bonded to a "focal plane array" ("FPA") and used to read-out (i.e., extract and register) signals produced by the detector | For the purposes of 6A002.f., a 'Read-Out Integrated Circuit' ('ROIC') is an integrated circuit designed to underlie or be bonded to a "focal plane array" ("FPA") and used to read-out (i.e., extract and register) signals |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| | 低限度的˝ROIC˝能透過擷取方式由探測元件讀取電荷，與應用多工功能方式維持探測元件中相對空間位置與方向資訊，以利在˝ROIC˝內部或外部進行處理。 | 所產生的訊號，最低限度的˝ROIC˝能透過擷取方式由探測元件讀取電荷，與應用多工功能方式維持探測元件中相對空間位置與方向資訊，以利在˝ROIC˝內部或外部進行處理。 | elements. At a minimum the 'ROIC' reads the charge from the detector elements by extracting the charge and applying a multiplexing function in a manner that retains the relative spatial position and orientation information of the detector elements for processing inside or outside the 'ROIC'. | produced by the detector elements. At a minimum the 'ROIC' reads the charge from the detector elements by extracting the charge and applying a multiplexing function in a manner that retains the relative spatial position and orientation information of the detector elements for processing inside or outside the 'ROIC'. |
| 6A003.b.1 技術註解 | 1. 為上述之目的，數位攝影機需以能捕捉移動影像之最大˝主動像素″評估之。<br>2. 為上述之目的，˝攝影追蹤資料˝係指可以定義攝影機觀測線相對於地球方位所需之資訊，包括：1)攝影機觀測線相對於地球磁場方向之水平角度；及2)攝影機觀測線與地平線之垂直角度。 | 1. 就6A003.b.1.目的，數位攝影機需以能捕捉移動影像之最大˝主動像素″評估之。<br>2. 就6A003.b.1.b.3.目的，˝攝影追蹤資料˝係指可以定義攝影機觀測線相對於地球方位所需之資訊，包括：1)攝影機觀測線相對於地球磁場方向之水平角度；及2)攝影機觀測線與地平線之垂直角度。 | 1.For the purpose of this entry, digital video cameras should be evaluated by the maximum number of "active pixels" used for capturing moving images.<br><br>2.For the purpose of this entry, 'camera tracking data' is the information necessary to define camera line of sight orientation with respect to the earth. This includes: 1) the horizontal angle the camera line of sight makes with respect to the earth's magnetic field direction and; 2) the vertical angle between the camera line of sight and the earth's horizon. | 1.For the purposes of 6A003.b.1., digital video cameras should be evaluated by the maximum number of "active pixels" used for capturing moving images.<br><br>2.For the purposes of 6A003.b.1.b.3., 'camera tracking data' is the information necessary to define camera line of sight orientation with respect to the earth. This includes: 1) the horizontal angle the camera line of sight makes with respect to the earth's magnetic field direction and; 2) the vertical angle between the camera line of sight and the earth's horizon. |
| 6A003.b.4 註解 3 技術註解 | 1. 6A003.b.4.註解 3.b.所述之˝瞬間視場 (IFOV)˝，為˝水平 IFOV˝或˝垂直 IFOV˝數值較小者。<br>˝水平 IFOV˝ =水平視場 (FOV)/水平偵測元件數<br>˝垂直 IFOV˝ =垂直視場 (FOV)/垂直偵測元件數<br>2. 6A003.b.4.註解 3.b.所述之˝直視˝指影像照相機於紅外線光譜下操作，並呈現可見影像予使用內含光安全裝置之近眼式微顯示器之觀測者。 | 1. 就6A003.b.4.註解 3.b.1.目的，˝瞬間視場 (IFOV)˝，為˝水平 IFOV˝或˝垂直 IFOV˝數值較小者。<br>˝水平 IFOV˝ =水平視場 (FOV)/水平偵測元件數<br>˝垂直 IFOV˝ =垂直視場 (FOV)/垂直偵測元件數<br>2. 就6A003.b.4.註解 3.b.3.目的，˝直視˝指影像照相機於紅外線光譜下操作，並呈現可見影像予使用內含光安全裝置之近眼式微顯示器之觀測者。 | 1. 'Instantaneous Field of View (IFOV)' specified in 6A003.b.4. Note 3.b. is the lesser figure of the 'Horizontal IFOV' or the 'Vertical IFOV'.<br><br>'Horizontal IFOV' = horizontal Field of View (FOV) / number of horizontal detector elements<br><br>'Vertical IFOV' = vertical Field of View (FOV) / number of vertical detector elements.<br><br>2. 'Direct view' in 6A003.b.4. Note | 1. For the purposes of 6A003.b.4. Note 3.b.1. 'Instantaneous Field of View (IFOV)' is the lesser figure of the 'Horizontal IFOV' or the 'Vertical IFOV'.<br><br>'Horizontal IFOV' = horizontal Field of View (FOV) / number of horizontal detector elements<br><br>'Vertical IFOV' = vertical Field of View (FOV) / number of vertical detector elements.<br><br>2. For the purposes of 6A003.b.4. Note |

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| | | | 3.b. refers to an imaging camera operating in the infrared spectrum that presents a visual image to a human observer using a near-to-eye micro display incorporating any light-security mechanism. | 3.b.3. 'direct view' refers to an imaging camera operating in the infrared spectrum that presents a visual image to a human observer using a near-to-eye micro display incorporating any light-security mechanism. |
| 6A004.a.1 技術註解 | ˋ可變形鏡面´為鏡片具下列任一特性者： | 就 6A004.a.目的，ˋ可變形鏡面´為鏡片具下列任一特性者： | 'Deformable mirrors' are mirrors having any of the following: | For the purposes of 6A004.a.1., 'deformable mirrors' are mirrors having any of the following: |
| 6A004.e 技術註解 | 1. ˋ非球面光學元件´係指使用在一光學系統，其表面設計為偏離理想球狀外形之任何元件。<br>2. 除非光學元件為符合或超越控制參數而設計或製造，否則廠商無需被要求依 6A004.e.2.之標準來度量表面粗糙度。 | 1. 就 6A004.e.目的，ˋ非球面光學元件´係指使用在一光學系統，其表面設計為偏離理想球狀外形之任何元件。<br>2. 就 6A004.e.目的，除非光學元件為符合或超越控制參數而設計或製造，否則廠商無需被要求依 6A004.e.2.之標準來度量表面粗糙度。 | 1.An 'aspheric optical element' is any element used in an optical system whose imaging surface or surfaces are designed to depart from the shape of an ideal sphere.<br><br>2.Manufacturers are not required to measure the surface roughness listed in 6A004.e.2. unless the optical element was designed or manufactured with the intent to meet, or exceed, the control parameter. | 1.For the purposes of 6A004.e., an 'aspheric optical element' is any element used in an optical system whose imaging surface or surfaces are designed to depart from the shape of an ideal sphere.<br><br>2.For the purposes of 6A004.e.2., manufacturers are not required to measure the surface roughness unless the optical element was designed or manufactured with the intent to meet, or exceed, the control parameter. |
| 6A005 註解 2 技術註解 | ˋ非重複性脈衝´指〝雷射〞產生單一脈衝輸出或在脈衝之時間其間隔超過 1 分鐘。 | 就 6A005 註解 2.目的，ˋ非重複性脈衝´指〝雷射〞產生單一脈衝輸出或在脈衝之時間其間隔超過 1 分鐘。 | 'Non-repetitive pulsed' refers to "lasers" that produce either a single output pulse or that have a time interval between pulses exceeding one minute. | For the purposes of 6A005Note 2.,'non-repetitive pulsed' refers to "lasers" that produce either a single output pulse or that have a time interval between pulses exceeding one minute. |
| 6A005 技術註解 | 6A005 ˋ功率轉換效率´之定義為〝雷射〞輸出功率(或平均輸出功率)與操作〝雷射〞所需輸入總電功率之比率，包括電源供應與調整以及熱能調整與熱轉換器。 | 就 6A005 目的，ˋ功率轉換效率´之定義為〝雷射〞輸出功率(或平均輸出功率)與操作〝雷射〞所需輸入總電功率之比率，包括電源供應與調整以及熱能調整與熱轉換器。 | In 6A005 'Wall-plug efficiency' is defined as the ratio of "laser" output power (or "average output power") to total electrical input power required to operate the "laser", including the power supply/conditioning and thermal condition- ing/heat exchanger. | For the purposes of 6A005, 'wall-plug efficiency' is defined as the ratio of "laser" output power (or "average output power") to total electrical input power required to operate the "laser", including the power supply/conditioning and thermal condition- ing/heat exchanger. |
| 6A005.b.3.a.2 | 〝平均輸出功率〞超過 50 W；或 | 2. 〝平均輸出功率〞超過 80 W；或 | "Average output power" exceeding 50 W; or | "Average output power" exceeding 80 W; or |

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| 6A005.d.1.a.1 | 波長等於或小於 1,510 nm，且平均或連續波之輸出功率超過 1.5 W；或 | 1. 波長等於或小於 1,570 nm，且平均或連續波之輸出功率超過 2.0 W；或 | Wavelength equal to or less than 1 510 nm and average or CW output power, exceeding 1,5 W; or | Wavelength equal to or less than 1 570 nm and average or CW output power, exceeding 2,0 W; or |
| 6A005.d.1.a.2 | 波長大於 1,510 nm，且平均或連續波輸出功率超過 500 mW； | 2. 波長大於 1,570 nm，且平均或連續波輸出功率超過 500 mW； | Wavelength greater than 1 510 nm and average or CW output power, exceeding 500 mW; | Wavelength greater than 1 570 nm and average or CW output power, exceeding 500 mW; |
| 6A005.d.1.e 技術註解 | 1. 半導體〝雷射〞，通稱為〝雷射〞二極體。<br>2. 1 個˙棒˙(又稱半導體雷射棒、雷射二極體棒、二極體棒)係由多個半導體〝雷射〞發射器組合成一維陣列。<br>3. 1 個˙陣列疊˙由多個˙棒˙組合形成一個半導體〝雷射〞之 2 維陣列。 | 就 6A005.d.1.e.目的：<br>1. 半導體〝雷射〞，通稱為〝雷射〞二極體。<br>2. 1 個˙棒˙(又稱半導體雷射棒、雷射二極體棒、二極體棒)係由多個半導體〝雷射〞發射器組合成一維陣列。<br>3. 1 個˙陣列疊˙由多個˙棒˙組合形成一個半導體〝雷射〞之 2 維陣列。 | 1. Semiconductor "lasers" are commonly called "laser" diodes.<br><br>2. A 'bar' (also called a semiconductor "laser" 'bar', a "laser" diode 'bar' or diode 'bar') consists of multiple semiconductor "lasers" in a one-dimensional array.<br><br>3. A 'stacked array' consists of multiple 'bars' forming a two-dimensional array of semiconductor "lasers". | For the purposes of 6A005.d.1.e.:<br><br>1. Semiconductor "lasers" are commonly called "laser" diodes.<br><br>2. A 'bar' (also called a semiconductor "laser" 'bar', a "laser" diode 'bar' or diode 'bar') consists of multiple semiconductor "lasers" in a one-dimensional array.<br><br>3. A 'stacked array' consists of multiple 'bars' forming a two-dimensional array of semiconductor "lasers". |
| 6A005.d.5.c 技術註解 | ˙移轉雷射˙指具雷射發光性能之原子或分子碰撞不具雷射發光性能之原子或分子，產生之能量移轉而激發的一種〝雷射〞。 | 就 6A005.d.5.c.目的，˙移轉雷射˙指具雷射發光性能之原子或分子碰撞不具雷射發光性能之原子或分子，產生之能量移轉而激發的一種〝雷射〞。 | 'Transfer lasers' are "lasers" in which the lasing species are excited through the transfer of energy by collision of a non- lasing atom or molecule with a lasing atom or molecule species. | For the purposes of 6A005.d.5.c., 'transfer lasers' are "lasers" in which the lasing species are excited through the transfer of energy by collision of a non-lasing atom or molecule with a lasing atom or molecule species. |
| 6A005.e.1 技術註解 | ˙主動式冷卻˙係指用於光學零件之冷卻技術，該技術使用流體於光學零件表面內層(一般是在光學設備之表面以下小於 1 mm)流動，以從光學設備移除熱量。 | 就 6A005.e.1.目的，˙主動式冷卻˙係指用於光學零件之冷卻技術，該技術使用流體於光學零件表面內層(一般是在光學設備之表面以下小於 1 mm)流動，以從光學設備移除熱量。 | 'Active cooling' is a cooling technique for optical components using flowing fluids within the subsurface (nominally less than 1 mm below the optical surface) of the optical component to remove heat from the optic. | For the purposes of 6A005.e.1., 'active cooling' is a cooling technique for optical components using flowing fluids within the subsurface (nominally less than 1 mm below the optical surface) of the optical component to remove heat from the optic. |

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| 6A005.g 技術註解 | ˋ雷射聲學偵測設備ˊ有時被稱為〝雷射〞麥克風或粒子流偵測麥克風。 | 就 6A005.g.目的，ˋ雷射聲學偵測設備ˊ有時被稱為〝雷射〞麥克風或粒子流偵測麥克風。 | 'Active cooling' is a cooling technique for optical components using flowing fluids within the subsurface (nominally less than 1 mm below the optical surface) of the optical component to remove heat from the optic. | For the purposes of 6A005.g., 'laser acoustic detection equipment' is sometimes referred to as a "Laser" Microphone or Particle Flow Detection Microphone. |
| 6A008.b 技術註解 | ˋ中心操作頻率ˊ為最高設定操作頻率與最低設定操作頻率之和的一半。 | 就 6A008.b.目的，ˋ中心操作頻率ˊ為最高設定操作頻率與最低設定操作頻率之和的一半。 | The 'centre operating frequency' equals one half of the sum of the highest plus the lowest specified operating frequencies. | For the purposes of 6A008.b., the 'centre operating frequency' equals one half of the sum of the highest plus the lowest specified operating frequencies. |
| 6A008.e 技術註解 | 電子掃描陣列天線亦稱為電子操控陣列天線。 | 就 6A008.e.目的，電子掃描陣列天線亦稱為電子操控陣列天線。 | Electronically scanned array antennae are also known as electronically steerable array antennae. | For the purposes of 6A008.e., electronically scanned array antennae are also known as electronically steerable array antennae. |
| 6A008.1.1 技術註解 | 自動目標追蹤〞乃一種處理技術，可自動決定並提供目標最可能的即時位置之推測值。 | 就 6A008.l.1.目的，〝自動目標追蹤〞乃一種處理技術，可自動決定並提供目標最可能的即時位置之推測值。 | 'Automatic target tracking' is a processing technique that automatically determines and provides as output an extrapolated value of the most probable position of the target in real time. | For the purposes of 6A008.l.1., 'automatic target tracking' is a processing technique that automatically determines and provides as output an extrapolated value of the most probable position of the target in real time. |
| 6A008.1.4 技術註解 | 〝地理分散〞指感應器相對位置在任一方向之距離均大於過 1,500 公尺。活動式感應器通常被視為 〝地理分散〞。 | 就 6A008.l.4.目的，〝地理分散〞指感應器相對位置在任一方向之距離均大於過 1,500 公尺。活動式感應器通常被視為 〝地理分散〞。 | Sensors are considered 'geographically dispersed' when each location is distant from any other more than 1 500 m in any direction. Mobile sensors are always considered 'geographically dispersed'. | For the purposes of 6A008.l.4., sensors are considered 'geographically dispersed' when each location is distant from any other more than 1 500 m in any direction. Mobile sensors are always considered 'geographically dispersed'. |
| 6B007 | 用於生產、調整和校準地面專用重力儀之設備，其靜態〝準確度(或稱〝精度〞)〞優於 0.1 mGal。 | 用於生產、調整和校準地面專用重力儀之設備，其靜態〝準確度(或稱〝精度〞)〞小於(優於)0.1 mGal。 | Equipment to produce, align and calibrate land-based gravity meters with a static "accuracy" of better than 0,1 mGal. | Equipment to produce, align and calibrate land-based gravity meters with a static "accuracy" of less (better) than 0,1 mGal. |
| 6C002.b | ˋ摩爾分數ˊ係指碲化鋅摩爾對呈現於晶體中之碲化鎘摩爾與碲化鋅摩爾總和之比例。 | 就 6C002.b.1.目的，ˋ摩爾分數ˊ係指碲化鋅摩爾對呈現於晶體中之碲化鎘摩爾與碲化鋅摩爾總和之比例。 | 'Mole fraction' is defined as the ratio of moles of ZnTe to the sum of moles of CdTe and ZnTe present in the crystal. | For the purposes of 6C002.b.1., 'mole fraction' is defined as the ratio of moles of ZnTe to the sum of moles of CdTe and ZnTe present in the crystal. |

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| 6C005.b.2 技術註解 | 1.就 6C005 目的，核心之﹨數值孔徑﹨（﹨NA﹨）以光纖的發射波長量測。<br>2. 6C005.b.包括光纖有裝配端帽者。 | 就 6C005.b.1.b.目的，核心之﹨數值孔徑﹨（﹨NA﹨）以光纖的發射波長量測。 | 1. For the purposes of 6C005, the core 'Numerical Aperture' ('NA') is measured at the emission wave-lengths of the fibre.<br>2 6C005.b. includes fibres assembled with end caps. | 1. For the purposes of 6C005.b.1.b., the core 'Numerical Aperture' ('NA') is measured at the emission wave-lengths of the fibre.<br>2 6C005.b. includes fibres assembled with end caps. |
| 6D003.h.2.b 技術註解 | 6D003.h.2.b.所述之﹨平均旁瓣水平﹨係指測量全部陣列，但不包括主光束及主光束任一側之首二旁瓣之角範圍。 | 就 6D003.h.2.b.目的，﹨平均旁瓣水平﹨係指測量全部陣列，但不包括主光束及主光束任一側之首二旁瓣之角範圍。 | 'Average side lobe level' in 6D003.h.2.b. is measured over the entire array excluding the angular extent of the main beam and the first two side lobes on either side of the main beam. | For the purposes of 6D003.h.2.b., 'average side lobe level' in 6D003.h.2.b. is measured over the entire array excluding the angular extent of the main beam and the first two side lobes on either side of the main beam. |
| 6E003.a.1 技術註解 | ﹨光學厚度﹨指產品折射率乘以鍍膜實體厚度之數學乘積。 | 就 6E003.a.1.目的，﹨光學厚度﹨指產品折射率乘以鍍膜實體厚度之數學乘積。 | 'Optical thickness' is the mathematical product of the index of refraction and the physical thickness of the coating. | For the purposes of 6E003.a.1., 'optical thickness' is the mathematical product of the index of refraction and the physical thickness of the coating. |
| 7A003 註解 | 註解 1：﹨慣性測量設備或系統﹨包含加速度計或陀螺儀測量速度與方向之變化，以確定或維持航向或位置，而無須使用外部基準進行對準。﹨慣性測量設備或系統﹨，包括：<br>—姿航與航向參考系統(AHRSs)；<br>—陀螺羅盤；<br>—慣性測量單元(IMU)；<br>—慣性導航系統(INSs)；<br>—慣性參考系統(IRSs)；<br>—慣性參考單元(IRUs)；<br>註解 2：7A003 不管制﹨慣性測量設備或系統﹨，其為〝民用航空器〞使用並經過 1 個或以上〝歐盟會員國〞或瓦聖那協議之締約國民航主管機關認證。 | 註解：7A003 不管制﹨慣性測量設備或系統﹨，其為〝民用航空器〞使用並經過 1 個或以上〝歐盟會員國〞或瓦聖那協議之締約國民航主管機關認證。 | Note 1:Inertial measurement equipment or systems' incorporate accelerometers or gyroscopes to measure changes in velocity and orientation in order to determine or maintain heading or position without requiring an external reference once aligned. 'Inertial measurement equipment or systems' include:<br>— Attitude and Heading Reference Systems (AHRSs);<br>— Gyrocompasses;<br>— Inertial Measurement Units (IMUs);<br>— Inertial Navigation Systems (INSs);<br>— Inertial Reference Systems (IRSs);<br>— Inertial Reference Units (IRUs).<br>Note 2:7A003 does not control 'inertial measurement equipment or systems' which are certified for use on "civil aircraft" by civil aviation | Note :7A003. does not apply to 'inertial measurement equipment or systems' which are certified for use on "civil aircraft" by civil aviation authorities of one or more EU Member States or Wassenaar Arrangement Participating States. |

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| | | | authorities of one or more "EU Member States or Wassenaar Arrangement Participating States. | |
| 7A003 技術註解 | 在 7A003.a.1.、7A003.a.2.與 7A003.a.3.之中的性能指標,通常應用於〝慣性測量設備或系統〞,其設計用於〝航空器〞、陸上載具或船舶,其參數來自於運用非位置輔助參考(即高度計、里程表、速度測錄),上述不同平台之參數之間不能輕易轉換。設計用於多平台之設備,針對其適用性,以 7A003.a.1.、7A003.a.2.或 7A003.a.3.進行評估。 | 1.就 7A003 目的,〝慣性測量設備或系統〞包含加速度計或陀螺儀測量速度與方向之變化,以確定或維持航向或位置,而無須使用外部基準進行對準。〝慣性測量設備或系統〞,包括:<br>—姿航與航向參考系統(AHRSs);<br>—陀螺羅盤;<br>—慣性測量單元(IMU);<br>—慣性導航系統(INSs);<br>—慣性參考系統(IRSs);<br>—慣性參考單元(IRUs);<br>2.就 7A003 目的,〝慣性測量設備或系統〞提供位置,及包括:<br>a.〝衛星導航系統〞;<br>b.〝資料庫參考導航〞(〝DBRN〞)。 | 'Positional aiding references' independently provide position, and include:<br><br>a.Global Navigation Satellite Systems (GNSS);<br><br>b."Data-Based Referenced Navigation" ("DBRN"). | 1. For the purposes of 7A003, inertial measurement equipment or systems' incorporate accelerometers or gyroscopes to measure changes in velocity and orientation in order to determine or maintain heading or position without requiring an external reference once aligned. 'Inertial measurement equipment or systems' include:<br><br>— Attitude and Heading Reference Systems (AHRSs);<br><br>— Gyrocompasses;<br><br>— Inertial Measurement Units (IMUs);<br><br>— Inertial Navigation Systems (INSs);<br><br>— Inertial Reference Systems (IRSs);<br><br>— Inertial Reference Units (IRUs).<br><br>2. For the purposes of 7A003, 'positional aiding references' independently provide position, and include:<br>a. "Satellite navigation system";<br>b. "Data-Based Referenced Navigation" ("DBRN"). |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| 7A003.a 技術註解 | 在7A003.a.1.、7A003.a.2.與7A003.a.3.之中的性能指標，通常應用於˝慣性測量設備或系統˝，其設計用於˝航空器˝、陸上載具或船舶，其參數來自於運用非位置輔助參考(即高度計、里程表、速度測錄)，上述不同平台之參數之間不能輕易轉換。設計用於多平台之設備，針對其適用性，以7A003.a.1.、7A003.a.2.或7A003.a.3.進行評估。 | 就7A003.a.1.、7A003.a.2.與7A003.a.3.目的，性能指標通常應用於˝慣性測量設備或系統˝，其設計用於˝航空器˝、陸上載具或船舶，其參數來自於運用非位置輔助參考(即高度計、里程表、速度測錄)，上述不同平台之參數之間不能輕易轉換。設計用於多平台之設備，針對其適用性，以7A003.a.1.、7A003.a.2.或7A003.a.3.進行評估。 | The performance parameters in 7A003.a.1., 7A003.a.2. and 7A003.a.3. typically apply to 'inertial measurement equipment or systems' designed for "aircraft", vehicles and vessels, respectively. These parameters result from the utilisation of specialised non-positional aiding references (e.g., altimeter, odometer, velocity log). As a consequence, the specified performance values cannot be readily converted between these parameters. Equipment designed for multiple platforms are evaluated against each applicable entry 7A003.a.1., 7A003.a.2., or 7A003.a.3. | For the purposes of 7A003.a.1., 7A003.a.2. and 7A003.a.3.,The performance parameters typically apply to 'inertial measurement equipment or systems' designed for "aircraft", vehicles and vessels, respectively. These parameters result from the utilisation of specialised non-positional aiding references (e.g., altimeter, odometer, velocity log). As a consequence, the specified performance values cannot be readily converted between these parameters. Equipment designed for multiple platforms are evaluated against each applicable entry 7A003.a.1., 7A003.a.2., or 7A003.a.3. |
| 7A003.b 技術註解 | 在7A003.b.指一系統，其將˝慣性測量設備或系統˝及˝位置輔助參考˝建立於同一單元中(即嵌入式)以實現增進性能。 | 就7A003.b.目的,指一系統,其將˝慣性測量設備或系統˝及˝位置輔助參考˝建立於同一單元中(即嵌入式)以實現增進性能。 | 7A003.b. refers to systems in which 'inertial measurement equipment or systems' and other independent 'positional aiding references' are built into a single unit (i.e., embedded) in order to achieve improved performance. | For the purposes of 7A003.b., this entry refers to systems in which 'inertial measurement equipment or systems' and other independent 'positional aiding references' are built into a single unit (i.e., embedded) in order to achieve improved performance. |
| 7A004 技術註解 | ˝星體追蹤儀˝亦稱為星體姿態感測器或迴轉天體羅盤。 | 就7A004.a.目的，˝星體追蹤儀˝亦稱為星體姿態感測器或迴轉天體羅盤。 | 'Star trackers' are also referred to as stellar attitude sensors or gyro-astro compasses. | For the purposes of 7A004.a.,'Star trackers' are also referred to as stellar attitude sensors or gyro-astro compasses. |
| 7A006 技術註解 | ˝功率管理˝指改變高度計訊號之傳輸功率，以致使˝航空器˝高度之接收功率總是在決定高度之最小需求。 | 就7A006.a.目的，˝功率管理˝指改變高度計訊號之傳輸功率,以致使˝航空器˝高度之接收功率總是在決定高度之最小需求。 | 'Power management' is changing the transmitted power of the altimeter signal so that received power at the "aircraft" altitude is always at the minimum necessary to determine the altitude. | For the purposes of 7A006.a.,'power management' is changing the transmitted power of the altimeter signal so that received power at the "aircraft" altitude is always at the minimum necessary to determine the altitude. |
| 7B001 技術註解 | 1. 維護等級I 慣性導航元件故障可由˝航空器˝之控制及顯示元件(CDU)指示或由對應之子系統狀態訊息偵知。依照製造商 | 就7B001目的: 1. 維護等級I 慣性導航元件故障可由˝航空器˝之控制及顯示元件(CDU)指示或由對應 | 1.    'Maintenance Level I' The failure of an inertial navigation unit is detected on the "aircraft" by indications from the Control and | For the purposes of 7B001: 1.    'Maintenance Level I' The failure of an inertial navigation unit |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| | 手冊，故障原因可局部區隔於故障之線上可換元件(LRU)層次，然後操作者移除線上可換元件 LRU，換上備用元件。<br>2. 維護等級 II<br>損壞之 LRU 被送至維修工廠(製造商或負責維護等級 II 之業者)，在維修工廠，故障之線上可換元件(LRU)以各種適當方式測試，驗證並查出故障之工廠可換組件(SRA)。維修工廠將其移除並換上可用之備用元件，將損壞之工廠可換組件(亦可能是整個 LRU)運交製造商。維護等級 II 不包括由工廠可換組件(SRA)拆裝或更換受管制之加速器或陀螺儀感應器。 | 之子系統狀態訊息偵知。依照製造商手冊，故障原因可局部區隔於故障之線上可換元件(LRU)層次，然後操作者移除線上可換元件 LRU，換上備用元件。<br>2. 維護等級 II<br>損壞之 LRU 被送至維修工廠(製造商或負責維護等級 II 之業者)，在維修工廠，故障之線上可換元件(LRU)以各種適當方式測試，驗證並查出故障之工廠可換組件(SRA)。維修工廠將其移除並換上可用之備用元件，將損壞之工廠可換組件(亦可能是整個 LRU)運交製造商。維護等級 II 不包括由工廠可換組件(SRA)拆裝或更換受管制之加速器或陀螺儀感應器。 | Display Unit (CDU) or by the status message from the corresponding sub-system. By following the manufacturer's manual, the cause of the failure may be localised at the level of the malfunctioning Line Replaceable Unit (LRU). The operator then removes the LRU and replaces it with a spare.<br><br>2. Maintenance Level II'<br><br>The defective LRU is sent to the maintenance workshop (the manufacturer's or that of the operator responsible for level II maintenance). At the maintenance workshop, the malfunctioning LRU is tested by various appropriate means to verify and localise the defective Shop Replaceable Assembly (SRA) module responsible for the failure. This SRA is removed and replaced by an operative spare. The defective SRA (or possibly the complete LRU) is then shipped to the manufacturer. 'Maintenance Level II' does not include the disassembly or repair of controlled accelerometers or gyro sensors. | is detected on the "aircraft" by indications from the Control and Display Unit (CDU) or by the status message from the corresponding sub-system. By following the manufacturer's manual, the cause of the failure may be localised at the level of the malfunctioning Line Replaceable Unit (LRU). The operator then removes the LRU and replaces it with a spare.<br><br>2. Maintenance Level II'<br><br>The defective LRU is sent to the maintenance workshop (the manufacturer's or that of the operator responsible for level II maintenance). At the maintenance workshop, the malfunctioning LRU is tested by various appropriate means to verify and localise the defective Shop Replaceable Assembly (SRA) module responsible for the failure. This SRA is removed and replaced by an operative spare. The defective SRA (or possibly the complete LRU) is then shipped to the manufacturer. 'Maintenance Level II' does not include the disassembly or repair of controlled accelerometers or gyro sensors. |
| 7D002 技術註解 | 姿態航向參考系統(˙AHRS˙)與慣性導航系統(INS)之差異一般在於˙AHRS˙提供姿態與航向資料，而通常不提供與 INS 相關之加速度、速度及位置資訊。 | 就 7D002 目的，姿態航向參考系統(˙AHRS˙)與慣性導航系統(INS)之差異一般在於˙AHRS˙提供姿態與航向資料，而通常不提供與 INS 相關之加速度、速度及位置資訊。 | 'AHRS' generally differ from Inertial Navigation Systems (INS) in that an 'AHRS' provides attitude and heading information and normally does not provide the acceleration, velocity and position information associated with an INS. | For the purposes of 7D002, 'AHRS' generally differ from Inertial Navigation Systems (INS) in that an 'AHRS' provides attitude and heading information and normally does not provide the acceleration, velocity and position information associated with an INS. |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| 7D004 註解 | 7D004 不管制一般電腦元件與公用事業(如輸入信號獲取、輸出信號傳輸、電腦程式、數據載入、內建測試、任務排程機制)之〝原始碼〞,其未提供專用於飛行控制系統之功能。 | 7D004 不管制一般電腦元件與公用事業(如輸入信號獲取、輸出信號傳輸、電腦"程式"、數據載入、內建測試、任務排程機制)之〝原始碼〞,其未提供專用於飛行控制系統之功能。 | 7D004. does not control "source code" associated with common computer elements and utilities (e.g., input signal acquisition, output signal transmission, computer program and data loading, built-in test, task scheduling mechanisms) not providing a specific flight control system function. | 7D004. does not control "source code" associated with common computer elements and utilities (e.g., input signal acquisition, output signal transmission, computer "program" and data loading, built-in test, task scheduling mechanisms) not providing a specific flight control system function. |
| 7E004.a.5 技術註解 | 〝主飛行控制〞指使用力/力矩產生器之〝航空器〞之穩定或操控,即空氣動力控制表面或推進力向量。 | 就 7E004.a.5.目的,〝主飛行控制〞指使用力/力矩產生器之〝航空器〞之穩定或操控,即空氣動力控制表面或推進力向量。 | 'Primary flight control' is "aircraft" stability or manoeuvring control using force/moment generators, i.e. aerodynamic control surfaces or propulsive thrust vectoring. | For the purposes of 7E004.a.5.,'primary flight control' is "aircraft" stability or manoeuvring control using force/moment generators, i.e. aerodynamic control surfaces or propulsive thrust vectoring. |
| 7E004.a.6 技術註解 | 〝飛行控制光學感應器陣列〞指由光學感測器分佈而形成之網路,使用〝雷射〞光束提供即時飛行控制資料於機上處理。 | 就 7E004.a.6.目的,〝飛行控制光學感應器陣列〞指由光學感測器分佈而形成之網路,使用〝雷射〞光束提供即時飛行控制資料於機上處理。 | A 'flight control optical sensor array' is a network of distributed optical sensors, using "laser" beams, to provide real-time flight control data for on-board processing. | For the purposes of 7E004.a.6., a 'flight control optical sensor array' is a network of distributed optical sensors, using "laser" beams, to provide real-time flight control data for on-board processing. |
| 7E004.b.7.a 技術註解 | 〝內迴路〞指〝主動飛行控制系統〞之功能,其自動執行機體穩定性控制。 | 就 7E004.b.7.a.目的,〝內迴路〞指〝主動飛行控制系統〞之功能,其自動執行機體穩定性控制。 | 'Inner-loop' refers to functions of "active flight control systems" that automate airframe stability controls. | For the purposes of 7E004.b.7.a.,'inner-loop' refers to functions of "active flight control systems" that automate airframe stability controls. |
| 7E004.b.7.b.2 技術註解 | 〝飛行器狀態異常變化〞包括飛行中結構損壞、失去發動機推力、禁用控制介面,或貨物裝載不穩定的位移。 | 就 7E004.b.7.b.2.目的,〝飛行器狀態異常變化〞包括飛行中結構損壞、失去發動機推力、禁用控制介面,或貨物裝載不穩定的位移。 | 'Abnormal changes in aircraft state' include in-flight structural damage, loss of engine thrust, disabled control surface, or destabilizing shifts in cargo load. | For the purposes of 7E004.b.7.b.2.,'abnormal changes in aircraft state' include in-flight structural damage, loss of engine thrust, disabled control surface, or destabilizing shifts in cargo load. |
| 7E004.b 註解 | 7E004.b.不管制一般電腦元件與公用事業(如輸入信號獲取、輸出信號傳輸、電腦程式、數據載入、內建測試、任務排程機制)之〝技術〞,其未提供專用於飛行控制系統之功能。 | 7E004.b.不管制一般電腦元件與公用事業(如輸入信號獲取、輸出信號傳輸、電腦〝程式〞、數據載入、內建測試、任務排程機制)之〝技術〞,其未提供專用於飛行控制系統之功能。 | 7E004.b. does not control "technology" associated with common computer elements and utilities (e.g., input signal acquisition, output signal transmission, computer program and data loading, built-in test, task scheduling mechanisms) not | 7E004.b. does not control "technology" associated with common computer elements and utilities (e.g., input signal acquisition, output signal transmission, computer "program" and data loading, built-in test, task scheduling mechanisms) not providing a specific |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| | | | providing a specific flight control system function. | flight control system function. |
| 7E004.c.3 技術註解 | 〝可變幾何機翼〞指使用後緣襟翼或調整片、前緣襟翼或軸鼻翼,其位置在飛行中可受控制。 | 就 7E004.c.3.目的,〝可變幾何機翼〞指使用後緣襟翼或調整片、前緣襟翼或軸鼻翼,其位置在飛行中可受控制。 | 'Variable geometry aerofoils' use trailing edge flaps or tabs, or leading edge slats or pivoted nose droop, the position of which can be controlled in flight. | For the purposes of 7E004.c.3.,'variable geometry aerofoils' use trailing edge flaps or tabs, or leading edge slats or pivoted nose droop, the position of which can be controlled in flight. |
| 8A001.c.1.c | c.具超過 1,000 m 之光學資料或指令連結; | c. 具超過 1,000 m 之無線光纖資料或指令連結; | c. Optical data or command link exceeding 1 000m; | c. Wireless optical data or command link exceeding 1 000m; |
| 8A002.a.4 技術註解 | 8A002.a.4.之目的不因 8C001 所述輸出〝複合泡材〞仍在製程中未達最後零件形式,而不受管制。 | 就 8A002.a.4.目的,不因 8C001 所述輸出〝複合泡材〞仍在製程中未達最後零件形式,而不受管制。 | The objective of 8A002.a.4. should not be defeated by the export of 'syntactic foam' specified in 8C001 when an intermediate stage of manufacture has been performed and it is not yet in the final component form. | For the purposes of 8A002.a.4., this entry should not be defeated by the export of 'syntactic foam' specified in 8C001 when an intermediate stage of manufacture has been performed and it is not yet in the final component form. |
| 8A002.i.2 技術註解 | 決定〝運動自由度〞時,只計算具比例相關動作控制且使用位置回授之功能。 | 就 8A002.i.2.目的,決定〝運動自由度〞時,只計算具比例相關動作控制且使用位置回授之功能。 | Only functions having proportionally related motion control using positional feedback are counted when determining the number of degrees of 'freedom of movement'. | For the purposes of 8A002.i.2., only functions having proportionally related motion control using positional feedback are counted when determining the number of degrees of 'freedom of movement'. |
| 8A002.o.2.b | 功率輸出超過 2.5 MW 之內部液冷(水冷)式電力推進引擎; | b. 功率輸出超過 2.5 MW 之內部液冷(水冷)式電力推進馬達; | b.Internally liquid-cooled electric propulsion engines with a power output exceeding 2,5 MW; | b.Internally liquid-cooled electric propulsion motors with a power output exceeding 2,5 MW; |
| 8A002.o.2.c | c. 功率輸出超過 0.1 MW 之〝超導性〞推進引擎或永久磁電推進引擎; | c. 功率輸出超過 0.1 MW 之〝超導性〞推進馬達; | c. "Superconductive" propulsion engines or permanent magnet electric propulsion engines, with a power output exceeding 0,1 MW; | c. "Superconductive" propulsion motors, with a power output exceeding 0,1 MW; |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| 8A002.o.3.b 技術註解 | 〝主動式噪音抑制或消除系統〞包含能直接對噪音來源產生抗噪音或抗振動訊號之電子控制系統，可主動減少設備振動。 | 就 8A002.o.3.b.目的，〝主動式噪音抑制或消除系統〞包含能直接對噪音來源產生抗噪音或抗振動訊號之電子控制系統，可主動減少設備振動。 | 'Active noise reduction or cancellation systems' incorporate electronic control systems capable of actively reducing equipment vibration by the generation of anti-noise or anti-vibration signals directly to the source. | For the purposes of 8A002.o.3.b.,'active noise reduction or cancellation systems' incorporate electronic control systems capable of actively reducing equipment vibration by the generation of anti-noise or anti-vibration signals directly to the source. |
| 8A002.o.4 | 無 | 4.專為潛水艇而設計、功率輸出超過 0.1MW 的永磁電推進馬達；<br>註解：8A002.o.4. 包括邊緣驅動推進系統。 | - | 4. Permanent magnet electric propulsion motors specially designed for submersible vehicles, having a power output exceeding 0,1MW;<br><br>Note: 8A002.o.4. includes rim-driven propulsion systems. |
| 8C001 技術註解 | 〝複合泡材〞由嵌入樹脂〝基材〞之塑膠或玻璃中空球狀物組成。 | 就 8C001 目的，〝複合泡材〞由嵌入樹脂〝基材〞之塑膠或玻璃中空球狀物組成。 | 'Syntactic foam' consists of hollow spheres of plastic or glass embedded in a resin "matrix". | For the purposes of 8C001,'syntactic foam' consists of hollow spheres of plastic or glass embedded in a resin "matrix". |
| 8E002.c.4 技術註解 | 〝小水線面載具〞由如下之公式界定：於操作設計吃水時之水線面積小於 2x(於操作設計吃水時之排水體積) 2/3。 | 就 8E002.c.4.目的，〝小水線面載具〞由如下之公式界定：於操作設計吃水時之水線面積小於 2x(於操作設計吃水時之排水體積) 2/3。 | A 'small waterplane area vessel' is defined by the following formula: waterplane area at an operational design draft less than 2x (displaced volume at the operational design draft) 2/3. | For the purposes of 8E002.c.4., a 'small waterplane area vessel' is defined by the following formula: waterplane area at an operational design draft less than 2x (displaced volume at the operational design draft) 2/3. |
| 9A001.a | a.包含任何 9E003.a.、9E003.h.或 9E003.i.所述之〝技術〞；或 | a.包含任何 9E003.a.、9E003.h.或 9E003.i.所述之〝技術〞；或 | a. Incorporating any of the "technologies" specified in 9E003.a., 9E003.h. or 9E003.i.; or | a. Incorporating any of the "technologies" specified in 9E003.a., 9E003.h. or 9E003.i.; or |
| 9A001.b | b.設計用於推動以 1 馬赫 (Mach 1)或以上之速率巡航超過 30 分鐘之〝航空器〞。 | b. 刪除。 | b.Designed to power an "aircraft" to cruise at Mach 1 or higher, for more than thirty minutes. | b.Not used. |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
|---|---|---|---|---|
| 9A003 | 特別設計之組件或零件,其併用任一9E003.a.、9E003.h.或 9E003.i.所述之〝技術〞,用於下列任一航空用燃氣渦輪發動機: | 特別設計之組件或零件,其併用任一9E003.a.、9E003.h. 9E003.i. 或 9E003.k,所述之〝技術〞,用於下列任一航空用燃氣渦輪發動機: | Specially designed assemblies or components, incorporating any of the "technologies" specified in 9E003.a., 9E003.h. or 9E003i., for any of the following aero gas turbine engines: | Specially designed assemblies or components, incorporating any of the "technologies" specified in 9E003.a., 9E003.h. or 9E003i., or 9E003.k, for any of the following aero gas turbine engines: |
| 9A007.e 技術註解 | 〝強力機械結合〞指結合力等於或大於推進劑強度。 | 就 9A007.e.目的,〝強力機械結合〞指結合力等於或大於推進劑強度。 | 'Strong mechanical bond' means bond strength equal to or more than propellant strength. | For the purposes of 9A007.e., a 'strong mechanical bond' means bond strength equal to or more than propellant strength. |
| 9A008.a 技術註解 | 〝強力機械結合〞意指結合力等於或大於推進劑強度。 | 就 9A008.a.目的,〝強力機械結合〞意指結合力等於或大於推進劑強度。 | 'Strong mechanical bond' means bond strength equal to or more than propellant strength. | For the purposes of 9A008.a., a 'strong mechanical bond' means bond strength equal to or more than propellant strength. |
| 9A008.b 技術註解 | 〝結構效率(PV/W)〞為爆發壓力(P)乘以壓力室體積(V),再除以總壓力室重量(W)。 | 就 9A008.b.目的,〝結構效率(PV/W)〞為爆發壓力(P)乘以壓力室體積(V),再除以總壓力室重量(W)。 | 'Structural efficiency ratio (PV/W)' is the burst pressure (P) multiplied by the vessel volume (V) divided by the total pressure vessel weight (W). | For the purposes of 9A008.b., 'structural efficiency ratio (PV/W)' is the burst pressure (P) multiplied by the vessel volume (V) divided by the total pressure vessel weight (W). |
| 9A115.a 技術註解 | 無 | 2.9A115.a 中規定的儀器和裝置包括安裝在有人駕駛飛機或無人駕駛飛行器上的儀器和裝置。 | - | 2.Apparatus and devices specified in 9A115.a include those installed on a manned aircraft or an unmanned aerial vehicle. |
| 9B005.a 技術註解 | 〝測試段尺寸〞指在最大測試截面位置的圓之直徑、正方型之一邊,或矩形之最長邊。 | 就 9B005.a. 註解目的,〝測試段尺寸〞指在最大測試截面位置的圓之直徑、正方型之一邊,或矩形之最長邊。 | 'Test section size' means the diameter of the circle, or the side of the square, or the longest side of the rectangle, at the largest test section location. | For the purposes of 9B005.a. Note, 'test section size' means the diameter of the circle, or the side of the square, or the longest side of the rectangle, at the largest test section location. |
| 9E001 | 依照一般技術註解,為〝開發〞9A001.b.、9A004 至 9A012、9A350、9B 或 9D 所述之設備或〝軟體〞之〝技術〞。 | 依照一般技術註解,為〝開發〞9A001.b.、9A004 至 9A012、9A350、9B 或 9D 所述之設備或〝軟體〞之〝技術〞。 | "Technology" according to the General Technology Note for the "development" of equipment or "software", specified in 9A001.b., 9A004 to 9A012, 9A350, 9B or 9D. | "Technology" according to the General Technology Note for the "development" of equipment or "software", specified in 9A001.b.,9A004 to 9A012, 9A350, 9B or 9D. |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| 9E002 | 依照一般技術註解，為〝生產〞9A001.b.、9A004 至 9A011、9A350 或 9B 所述設備之〝技術〞。 | 依照一般技術註解，為〝生產〞 ~~9A001.b.、~~9A004 至 9A011、9A350 或 9B 所述設備之〝技術〞。 | "Technology" according to the General Technology Note for the "production" of equipment specified in 9A001.b., 9A004 to 9A011, 9A350 or 9B. | "Technology" according to the General Technology Note for the "production" of equipment specified in ~~9A001.b.,~~9A004 to 9A011, 9A350 or 9B. |
| 9E003.a.2.e 技術註解 | 當發動機以"穩態模式"運行時，在"壓力增益燃燒"的燃燒過程中，其燃燒器出口處的整體平均停滯壓力大於燃燒器入口處的整體平均停滯壓力。 | 就 9E003.a.2.e.目的，當發動機以"穩態模式"運行時，在"壓力增益燃燒"的燃燒過程中，其燃燒器出口處的整體平均停滯壓力大於燃燒器入口處的整體平均停滯壓力。 | In 'pressure gain combustion' the bulk average stagnation pressure at the combustor outlet is greater than the bulk average stagnation pressure at the combustor inlet due primarily to the combustion process, when the engine is running in a "steady state mode" of operation. | For the purposes of 9E003.a.2.e., in 'pressure gain combustion' the bulk average stagnation pressure at the combustor outlet is greater than the bulk average stagnation pressure at the combustor inlet due primarily to the combustion process, when the engine is running in a "steady state mode" of operation. |
| 9E003.a.2 技術註解 | 1. 〝熱解偶襯墊〞為一襯墊至少具備一個支撐結構設計以承載機械負載，以及一個燃燒覆蓋層結構設計用於在燃燒產生熱時保護支撐結構。燃燒覆蓋層結構與支撐結構在相互之間具有獨立熱置換(基於熱負載的機械置換)，即其為熱解偶。<br>2. 〝燃燒室出口溫度〞為，當發動機在〝穩定狀態模式〞下運轉至認證之最大連續操作溫度時，燃燒室出口平面與渦輪機進氣導向葉片尖端(即依照 SAE APR 755A 所定義之 T40 發動機站量測)兩者間之主體平均氣流總(停滯)溫度。 | 1. 就 9E003.a.2.a.目的，〝熱解偶襯墊〞為一襯墊至少具備一個支撐結構設計以承載機械負載，以及一個燃燒覆蓋層結構設計用於在燃燒產生熱時保護支撐結構。燃燒覆蓋層結構與支撐結構在相互之間具有獨立熱置換(基於熱負載的機械置換)，即其為熱解偶。<br>2. 就 9E003.a.2.d.目的，〝燃燒室出口溫度〞為，當發動機在〝穩定狀態模式〞下運轉至認證之最大連續操作溫度時，燃燒室出口平面與渦輪機進氣導向葉片尖端(即依照 SAE APR 755A 所定義之 T40 發動機站量測)兩者間之主體平均氣流總(停滯)溫度。 | 1. 'Thermally decoupled liners' are liners that feature at least a support structure designed to carry mechanical loads and a combustion facing structure designed to protect the support structure from the heat of combustion. The combustion facing structure and support structure have independent thermal displacement (mechanical displacement due to thermal load) with respect to one another, i.e. they are thermally decoupled.<br><br>2. 'Combustor exit temperature' is the bulk average gas path total (stagnation) temperature between the combustor exit plane and the leading edge of the turbine inlet guide vane (i.e., measured at engine station T40 as defined in SAE ARP 755A) when the engine is running in a "steady state mode" of operation at the certificated maximum continuous operating temperature. | 1.For the purposes of 9E003.a.2.a.,'thermally decoupled liners' are liners that feature at least a support structure designed to carry mechanical loads and a combustion facing structure designed to protect the support structure from the heat of combustion. The combustion facing structure and support structure have independent thermal displacement (mechanical displacement due to thermal load) with respect to one another, i.e. they are thermally decoupled.<br><br>2. For the purposes of 9E003.a.2.d., 'combustor exit temperature' is the bulk average gas path total (stagnation) temperature between the combustor exit plane and the leading edge of the turbine inlet guide vane (i.e., measured at engine station T40 as defined in SAE ARP 755A) when the engine is running in a "steady state mode" of operation at the certificated maximum continuous |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| | | | | operating temperature. |
| 9E003.a.3.c 技術註解 | ˋ分離導管ˊ執行發動機主段與旁通段之間空氣質量之初始分離。 | 就 9E003.a.3.c.目的，ˋ分離導管ˊ執行發動機主段與旁通段之間空氣質量之初始分離。 | A 'splitter duct' performs the initial separation of the air-mass flow between the bypass and core sections of the engine. | For the purposes of 9E003.a.3.c., a 'splitter duct' performs the initial separation of the air-mass flow between the bypass and core sections of the engine. |
| 9E003.a.5 技術註解 | ˋ燃氣路徑溫度ˊ 為當發動機在ˋ穩定狀態模式ˊ下運轉至經認證或指定之最大連續操作溫度時，渦輪機元件前緣平面之主體平均氣流總(停滯)溫度。 | 就 9E003.a.5.目的，ˋ燃氣路徑溫度ˊ為當發動機在ˋ穩定狀態模式ˊ下運轉至經認證或指定之最大連續操作溫度時，渦輪機元件前緣平面之主體平均氣流總(停滯)溫度。 | 'Gas path temperature' is the bulk average gas path total (stagnation) temperature at the leading edge plane of the turbine component when the engine is running in a "steady state mode" of operation at the certificated or specified maximum continuous operating temperature. | For the purposes of 9E003.a.5.,'gas path temperature' is the bulk average gas path total (stagnation) temperature at the leading edge plane of the turbine component when the engine is running in a "steady state mode" of operation at the certificated or specified maximum continuous operating temperature. |
| 9E003.a.8 技術註解 | ˋ破壞容損ˊ零件之設計乃使用預測並限制裂紋擴大之方式以及經實證而成。 | 就 9E003.a.8.目的，ˋ破壞容損ˊ零件之設計乃使用預測並限制裂紋擴大之方式以及經實證而成。 | 'Damage tolerant' components are designed using methodology and substantiation to predict and limit crack growth. | For the purposes of 9E003.a.8.,'damage tolerant' components are designed using methodology and substantiation to predict and limit crack growth. |
| 9E003.c 技術註解 4 | 4.製造 9E003.c.所述孔洞之方法，包括〝雷射〞光束機械加工、水刀機械加工、電化學加工(ECM)或放電加工(EDM)。 | 4. 就 9E003.c.目的，製造 9E003.c.所述孔洞之方法，包括〝雷射〞光束機械加工、水刀機械加工、電化學加工(ECM)或放電加工(EDM)。 | 4.Methods for manufacturing holes in 9E003.c. include "laser" beam machining, water jet machining, Electro- Chemical Machining (ECM) or Electrical Discharge Machining (EDM). | 4.For the purposes of 9E003.c., methods for manufacturing holes in 9E003.c. include "laser" beam machining, water jet machining, Electro- Chemical Machining (ECM) or Electrical Discharge Machining (EDM). |
| 9E003.e 技術註解 | 於 9E003.e.中之ˋ箱體積ˊ為以下列方式所測得之 3 個相互垂直尺寸之乘積： | 就 9E003.e.目的，ˋ箱體積ˊ為以下列方式所測得之 3 個相互垂直尺寸之乘積： | 'Box volume' in 9E003.e. is the product of three perpendicular dimensions measured in the following way: | For the purposes of 9E003.e.,'box volume' in 9E003.e. is the product of three perpendicular dimensions measured in the following way: |
| 9E003.g 技術註解 | ˋ高輸出柴油發動機ˊ：若額定轉速為 2,300 r.p.m.或以上，而轉速在 2,300 r.p.m.時，其特定之制動平均有效壓力為 1.8 MPa 或以上之柴油發動機。 | 就 9E003.g.目的，ˋ高輸出柴油發動機ˊ：若額定轉速為 2,300 r.p.m.或以上，而轉速在 2,300 r.p.m.時，其特定之制動平均有效壓力為 1.8 MPa 或以 | 'High output diesel engines' are diesel engines with a specified brake mean effective pressure of 1,8 MPa or more at a speed of 2 300 r.p.m., provided the rated speed is 2 300 r.p.m. or more. | For the purposes of 9E003.g.,'high output diesel engines' are diesel engines with a specified brake mean effective pressure of 1,8 MPa or more at a speed of 2 300 r.p.m., provided the rated speed |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| | | 上之柴油發動機。 | | is 2 300 r.p.m. or more. |
| 9E003.k | 無 | k. 除 9E003.a.、9E003.h. 或 9E003.i. 所述以外，為能使〝航空器〞以 1 馬赫 或以上之速度巡航超過 30 分鐘而〝開發〞之以下任一專門設計用於航空燃氣渦輪發動機的組件或系統所〝必要〞之〝技術〞：<br><br>1.推進進氣道系統；<br>2.推進尾端出氣系統；<br>3.〝再加熱系統〞；<br>4. 監控潤滑或〝冷卻引擎轉子支撐座〞之〝主動式熱力管理系統〞；<br>5.無油式〝引擎轉子支撐座〞；或<br>6. 〝壓縮段〞主氣流道除熱系統。<br>技術註解：<br>就 9E003.k 目的：<br>1.推進進氣道系統包括主流道預冷器。<br>2. 〝再加熱系統〞應用燃燒尾端出氣系統或是由渦輪段後級及旁通流道流出之氣體提供額外推力。〝再加熱系統〞也稱為後燃器。<br>3.〝主動式熱力管理系統〞提供相較於被動式以油冷卻空氣或是以油冷卻燃油的不同方式，例如蒸汽循環系統。<br>4.〝壓縮段〞是指引擎進氣面和燃燒 | | k. "Technology", not specified in 9E003.a., 9E003.h., or 9E003.i., "required" for the "development" of any of the following components or systems, specially designed for aero gas turbine engines to enable "aircraft" to cruise at Mach 1or greater for more than 30minutes:<br><br>1.Propulsion inlet systems;<br><br>2.Propulsion exhaust systems;<br><br>3.'Reheat systems';<br><br>4.'Active thermal management systems' to condition fluids used to lubricate or cool 'engine rotor supports';<br><br>5.Oil-free 'engine rotor supports'; or<br><br>6.Systems to remove heat from 'compression system' core gas path flow.<br><br>Technical Notes:<br><br>For the purposes of 9E003.k.:<br><br>1.Propulsion inlet systems include core flow pre-coolers.<br><br>2.'Reheat systems' provide additional thrust by combusting fuel in exhaust and/or bypass flow downstream of the |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
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| | | 室之間任何階段或階段的組合透過機械增壓。<br><br>5. ˋ引擎轉子支撐座′是支撐驅動壓縮段或渦輪轉子的主機軸的軸承。<br><br>註解 1：參照 9E003.h。用於引擎控制技術。<br><br>註解 2：參照 9E003.i。用於可調整流量路徑系統技術。 | | last turbomachinery stage. 'Reheat systems' are also referred to as afterburners.<br><br>3.'Active thermal management systems' employ methods other than passive oil-to-air cooling or oil-to-fuel cooling, such as vapour cycle systems.<br><br>4.'Compression system' is any stage or combination of stages between the engine inlet face and the combustor that increases gas path pressure through mechanical work.<br><br>5.An 'engine rotor support' is the bearing supporting the main engine shaft that drives the compression system or turbine rotors.<br><br>NB1:See 9E003.h. for engine control technology.<br><br>NB2:See 9E003.i. for adjustable flow path systems technology. |
| 9E101 | 無 | ˋ技術′，如下： | - | "Technology" as follows: |

## 第二項：一般軍用貨品清單修正對照表

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
|---|---|---|---|---|
| ML8 註解 | 無 | ML8 子項中列出的任何物質均受此清單的約束，即使應用於指定用途之外（例如，TAGN 主要用作爆炸物，但也可用作燃料或氧化劑）。 | - | Any substance listed in the ML8 sub-items is subject to this list, even when utilised in an application other than that indicated (e.g., TAGN is predominantly used as an explosive but can also be used either as a fuel or an oxidiser). |
| ML8.d.3. 註解 3 | 無 | ML8.d.3.不管制五氟化碘 (CAS 7783-66-6)。 | - | ML8.d.3. does not apply to iodine pentafluoride (CAS 7783-66-6). |
| ML9.a.2.a. 技術註解 | ˋ底座ˊ指武器安裝點，或以裝設武器為目的加強結構。 | 就 ML9.a.2.a.目的，ˋ底座ˊ指武器安裝點，或以裝設武器為目的加強結構。 | 'Mountings' refers to weapon mounts or structural strengthening for the purpose of installing weapons. | For the purposes of ML9.a.2.a., 'mountings' refers to weapon mounts or structural strengthening for the purpose of installing weapons. |
| ML9.a.2.c.2. 技術註解 | 1. ˋCBRN 防護ˊ為含有加壓至過壓功能之室內空間，其具有隔離通風系統，有限的通風口裝設有 CBRN 濾網，且人員進入點具有氣閘；<br>2. ˋ預濕或沖洗系統ˊ為海水噴淋系統，可同時噴濕沖洗船隻之外部上層建築與甲板。 | 就 ML9.a.2.c.2.目的，ˋ預濕或沖洗系統ˊ為海水噴淋系統，可同時噴濕沖洗船隻之外部上層建築與甲板。 | 1. 'CBRN protection' is a self contained interior space containing features such as over-pressurization, isolation of ventilation systems, limited ventilation openings with CBRN filters and limited personnel access points incorporating air-locks.<br>2. 'Pre-wet or wash down system' is a seawater spray system capable of simultaneously wetting the exterior superstructure and decks of a vessel. | For the purposes of ML9.a.2.c.2., 'Pre-wet or wash down system' is a seawater spray system capable of simultaneously wetting the exterior superstructure and decks of a vessel. |
| ML9.a.2. 技術註解 | 無 | 就 ML9.a.2.目的，ˋCBRN 防護ˊ為含有加壓至過壓功能之室內空間，其具有隔離通風系統，有限的通風口裝設有 CBRN 濾網，且人員進入點具有 | - | For the purposes of ML9.a.2., 'CBRN protection' is a self-contained interior space containing features such as over-pressurization, isolation of ventilation systems, limited ventilation |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
|---|---|---|---|---|
| | | 氣閘。 | | openings with CBRN filters and limited personnel access points incorporating air-locks. |
| ML9.b.4.註解 | 無 | ML9.b.4.不管制核能。 | - | ML9.b.4. does not apply to nuclear power. |
| ML9.b.4.技術註解 | 〝絕氣推進〞(AIP)系統能使一潛入水中之潛艇在不使用大氣中氧氣的條件下操作其推進系統,並且能夠較電池等其他方法持續更長的時間。在 ML9.b.4.中,AIP 並不包含核能。 | 就 ML9.b.4.目的,〝絕氣推進〞(AIP)系統能使一潛入水中之潛艇在不使用大氣中氧氣的條件下操作其推進系統,並且能夠較電池等其他方法持續更長的時間。 | 'Air Independent Propulsion' (AIP) allows a submerged submarine to operate its propulsion system, without access to atmospheric oxygen, for a longer time than the batteries would have otherwise allowed. For the purposes of ML9.b.4., AIP does not include nuclear power. | For the purposes of ML9.b.4., 'AIP' allows a submerged submarine to operate its propulsion system, without access to atmospheric oxygen, for a longer time than the batteries would have otherwise allowed. |
| ML9.b.4.說明 | 無 | 請參閱 ML9.h。 核能推進設備。 | - | See ML9.h. for nuclear power propulsion equipment. |
| ML13.d. 註解 5 說明 | 針對雷射護目鏡請參照 ML17.o.。 | 針對〝雷射〞護目鏡請參照 ML17.o.。 | For laser protective eyewear, see ML17.o. | For "laser" protective eyewear, see ML17.o. |
| ML14 註解 3 | 無 | 〝軍事訓練之特殊設備〞包括軍用攻擊訓練器、作戰飛行訓練器、雷達定標訓練器、雷達定標產生器、射擊訓練裝置、反潛戰訓練器、飛行模擬器(包括飛行員/太空人訓練用之人員級離心機)、雷達訓練器、儀器飛行訓練器、導航訓練器、飛彈發射訓練器、定標設備、靶機(無人機)〝航空器〞、武裝訓練器、無人駕駛〝航空器〞訓練器、地面軍事行動之機動訓練單元及訓練設備。 | - | 'Specialised equipment for military training' includes military types of attack trainers, operational flight trainers, radar target trainers, radar target generators, gunnery training devices, anti-submarine warfare trainers, flight simulators (including human-rated centrifuges for pilot/astronaut training), radar trainers, instrument flight trainers, navigation trainers, missile launch trainers, target equipment, drone "aircraft", armament trainers, pilotless "aircraft" trainers, mobile training units and training equipment for ground military |

| 修正條目 | 現行內容 | 擬修正/新增內容 | 現行內容英譯 | 擬修正/新增內容英譯 |
|---|---|---|---|---|
| | | | | operations. |
| ML15 說明 | 參照軍商兩用貨品清單 6A002.a.2.及 6A002.b.。 | 參照軍商兩用貨品清單 6A002.a.、6A002.b 及 6A003.b.。 | See also entries 6A002.a.2. and 6A002.b. on the Dual-Use List. | See also entries 6A002.a.,6A002.b and 6A003.b. on the Dual-Use List. |
| ML17.e.3. 技術註解 | 電磁波脈衝非因接近電磁輻射設備附近（如機械、電器或電子產品）或照明之非故意干擾。 | 就 ML17.e.3.目的，電磁波脈衝非因接近電磁輻射設備附近（如機械、電器或電子產品）或照明之非故意干擾。 | Electro-magnetic pulse does not refer to unintentional interference caused by electromagnetic radiation from nearby equipment　(e.g. machinery, appliances or electronics) or lightning. | For the purposes of ML17.e.3., 'EMP' does not refer to unintentional interference caused by electromagnetic radiation from nearby equipment (e.g. machinery,　appliances or electronics) or lightning. |
| ML17.e.3. | 3. 特別設計或評定可在電磁脈衝(EMP)環境下操作； | 3. 特別設計或評定可在`電磁脈衝´(`EMP´)環境下操作； | 3. Specially designed or rated for operating in an electromagnetic pulse (EMP) environment; | 3. Specially designed or rated for operating in an 'Electromagnetic Pulse' (' EMP ') environment; |
| ML18 | a. 為`生產´一般軍用貨品清單所管制之產品而特別設計或改裝之`生產´設備，及其特別設計零件；<br>b. 其他地方未明確律定，係專為一般軍用貨品清單所管制貨品進行認證、合格鑑定或測試，而特別設計之環境測試設施及其特別設計之設備。 | a. 為`生產´一般軍用貨品清單所管制之產品而特別設計或改裝之設備，及其為此特別設計之零件；<br>b.專為一般軍用貨品清單所管制貨品進行認證、合格鑑定或測試，而特別設計之環境測試設施及其特別設計之設備，以及其他地方未列明的為此專門設計的設備。 | a. Specially designed or modified 'production' equipment for the 'production' of products specified by the Common Military List, and specially designed components therefor;<br>b. Specially designed environmental test facilities and specially designed equipment therefor, not specified elsewhere, for the certification, qualification or testing of products specified by the Munitions List. | a.Equipment specially designed or modified for the 'production' of items specified by the Munitions List, and specially designed components therefor;<br><br>b.Environmental test facilities specially designed for the certification, qualification or testing of items specified by the Munitions List, and specially designed equipment therefor, not specified elsewhere. |